

FEATURES

- Integrated fractional-N phase-locked loop (PLL)**
- RF input frequency range: 700 MHz to 2700 MHz**
- Internal local oscillator (LO) frequency range: 350 MHz to 2850 MHz**
- Input P1dB: 17 dBm**
- Output IP3: 45 dBm**
- Single-pole four-throw (SP4T) RF input switch**
- Digital step attenuator (DSA) range: 0 dB to 15 dB**
- Integrated RF tunable balun allowing single-ended 50 Ω input**
- Multicore integrated voltage controlled oscillator (VCO)**
- Digitally programmable variable gain amplifier (DGA)**
 - 3 dB bandwidth: >600 MHz
- Balanced 150 Ω IF output impedance**
- Programmable via 3-wire serial port interface (SPI)**
- Single 5 V supply**

APPLICATIONS

- Wireless receivers**
- Digital predistortion (DPD) receivers**

GENERAL DESCRIPTION

The [ADRF6620](#) is a highly integrated active mixer and synthesizer that is ideally suited for wireless receiver subsystems. The feature rich device consists of a high linearity broadband active mixer; an integrated fractional-N PLL; low phase noise, multicore VCO; and IF DGA. In addition, the [ADRF6620](#) integrates a 4:1 RF switch, an on-chip tunable RF balun, programmable RF attenuator, and low dropout (LDO) regulators. This highly integrated device fits within a small 7 mm × 7 mm footprint.

The high isolation 4:1 RF switch and on-chip tunable RF balun enable the [ADRF6620](#) to support four single-ended 50 Ω terminated RF inputs. A programmable attenuator ensures optimal RF input drive to the high linearity mixer core. The integrated DSA has an attenuation range of 0 dB to 15 dB with a step size of 1 dB.

FUNCTIONAL BLOCK DIAGRAM

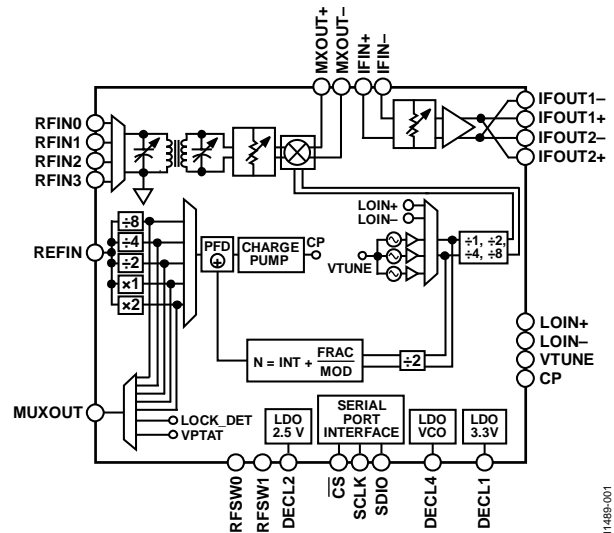


Figure 1.

The [ADRF6620](#) offers two alternatives for generating the differential LO input signal: externally, via a high frequency, low phase noise LO signal, or internally, via the on-chip fractional-N PLL synthesizer. The integrated synthesizer enables continuous LO coverage from 350 MHz to 2850 MHz. The PLL reference input can support a wide frequency range because the divide and multiply blocks can be used to increase or decrease the reference frequency to the desired value before it is passed to the phase frequency detector (PFD).

The integrated high linearity DGA provides an additional gain range from 3 dB to 15 dB in steps of 0.5 dB for maximum flexibility in driving an analog-to-digital converter (ADC).

The [ADRF6620](#) is fabricated using an advanced silicon-germanium BiCMOS process. It is available in a 48-lead, RoHS-compliant, 7 mm × 7 mm LFCSP package with an exposed pad. Performance is specified over the –40°C to +85°C temperature range.

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REVISION HISTORY

7/13—Revision 0: Initial Version

SPECIFICATIONS

VCCx = 5 V, T_A = 25°C, unless otherwise noted.

Table 1.

| Parameter | Test Conditions/Comments | Min | Typ | Max | Unit |
|-----------------------------------|------------------------------|------|-----|------|------|
| LO INPUT | | | | | |
| Internal LO Frequency Range | LO_DIV_A = 00 | 350 | | 2850 | MHz |
| External LO Frequency Range | | 350 | | 3200 | MHz |
| LO Input Level | | -6 | 0 | +6 | dBm |
| LO Input Impedance | | | 50 | | Ω |
| RF INPUT | | | | | |
| Input Frequency | | 700 | | 2700 | MHz |
| Input Return Loss | | | 12 | | dB |
| Input Impedance | | | 50 | | Ω |
| RF DIGITAL STEP ATTENUATOR | | | | | |
| Attenuation Range | Step size = 1 dB | 0 | | 15 | dB |
| POWER SUPPLY | | | | | |
| Power Consumption | LO output buffer disabled | 4.75 | 5.0 | 5.25 | V |
| | External LO + IF DGA enabled | | 1.3 | | W |
| | Internal LO + IF DGA enabled | | 1.7 | | W |
| | Only IF DGA enabled | | 0.6 | | W |
| Power-Down Current | | | 6 | | mA |

RF INPUT TO IF DGA OUTPUT SYSTEM SPECIFICATIONS

VCCx = 5 V, T_A = 25°C, high-side LO injection, f_{IF} = 200 MHz, internal LO frequency, IF DGA output load = 150 Ω, and 2 V p-p differential output with third-order low-pass filter, unless otherwise noted. For mixer settings for maximum linearity, see Table 16. All losses from input and output traces and baluns are de-embedded from results

Table 2. RF Switch + Balun + RF Attenuator + Mixer + IF DGA

| Parameter | Test Conditions/Comments | Min | Typ | Max | Unit |
|---|--|-----|------|-----|------|
| DYNAMIC PERFORMANCE AT f_{RF} = 900 MHz | | | | | |
| Voltage Conversion Gain | f _{IF} = 200 MHz | | 12 | | dB |
| Output P1dB | | | 18 | | dBm |
| Output IP3 | 1 V p-p each output tone, 1 MHz tone spacing | | 43 | | dBm |
| Output IP2 | 1 V p-p each output tone, 1 MHz tone spacing | | 78 | | dBm |
| Noise Figure | Noise figure optimized | | 16 | | dB |
| DYNAMIC PERFORMANCE AT f_{RF} = 1900 MHz | | | | | |
| Voltage Conversion Gain | f _{IF} = 200 MHz | | 11 | | dB |
| Output P1dB | | | 18 | | dBm |
| Output IP3 | 1 V p-p each output tone, 1 MHz tone spacing | | 45 | | dBm |
| Output IP2 | 1 V p-p each output tone, 1 MHz tone spacing | | 75 | | dBm |
| Noise Figure | Noise figure optimized | | 18.5 | | dB |
| DYNAMIC PERFORMANCE AT f_{RF} = 2100 MHz | | | | | |
| Voltage Conversion Gain | f _{IF} = 200 MHz | | 10.5 | | dB |
| Output P1dB | | | 18 | | dBm |
| Output IP3 | 1 V p-p each output tone, 1 MHz tone spacing | | 45 | | dBm |
| Output IP2 | 1 V p-p each output tone, 1 MHz tone spacing | | 66 | | dBm |
| Noise Figure | Noise figure optimized | | 19 | | dB |
| DYNAMIC PERFORMANCE AT f_{RF} = 2700 MHz | | | | | |
| Voltage Conversion Gain | f _{IF} = 200 MHz | | 9 | | dB |
| Output P1dB | | | 18 | | dBm |
| Output IP3 | 1 V p-p each output tone, 1 MHz tone spacing | | 44 | | dBm |
| Output IP2 | 1 V p-p each output tone, 1 MHz tone spacing | | 74 | | dBm |
| Noise Figure | Noise figure optimized | | 21 | | dB |

SYNTHESIZER/PLL SPECIFICATIONS

VCCX = 5 V, TA = 25°C, fREF = 153.6 MHz, fREF power = 4 dBm, fPFD = 38.4 MHz, and loop filter bandwidth = 120 kHz, unless otherwise noted.

Table 3.

| Parameter | Test Conditions/Comments | Min | Typ | Max | Unit |
|------------------------------------|--|--------------|------|------|--------|
| PLL REFERENCE | | | | | |
| PLL Reference Frequency | | 12 | | 464 | MHz |
| PLL Reference Level | For PLL lock condition | -15 | +4 | +14 | dBm |
| PFD FREQUENCY | | | | | |
| | | 24 | | 58 | MHz |
| INTERNAL VCO RANGE | | | | | |
| | | 2800 | | 5700 | MHz |
| OPEN-LOOP VCO PHASE NOISE | | | | | |
| fVCO2 = 3.4 GHz | VTUNE = 2 V, LO_DIV_A = 00 | | | | |
| | 1 kHz offset | | -39 | | dBc/Hz |
| | 10 kHz offset | | -81 | | dBc/Hz |
| | 100 kHz offset | | -103 | | dBc/Hz |
| | 800 kHz offset | | -123 | | dBc/Hz |
| | 1 MHz offset | | -125 | | dBc/Hz |
| | 6 MHz offset | | -143 | | dBc/Hz |
| | 10 MHz offset | | -147 | | dBc/Hz |
| | 40 MHz offset | | -155 | | dBc/Hz |
| | VCO sensitivity (Kv) | | 88 | | MHz/V |
| fVCO1 = 4.6 GHz | 1 kHz offset | | -39 | | dBc/Hz |
| | 10 kHz offset | | -74 | | dBc/Hz |
| | 100 kHz offset | | -101 | | dBc/Hz |
| | 800 kHz offset | | -123 | | dBc/Hz |
| | 1 MHz offset | | -125 | | dBc/Hz |
| | 6 MHz offset | | -143 | | dBc/Hz |
| | 10 MHz offset | | -147 | | dBc/Hz |
| | 40 MHz offset | | -156 | | dBc/Hz |
| | VCO sensitivity (Kv) | | 89 | | MHz/V |
| | fVCO0 = 5.5 GHz | 1 kHz offset | | -39 | |
| 10 kHz offset | | | -69 | | dBc/Hz |
| 100 kHz offset | | | -99 | | dBc/Hz |
| 800 kHz offset | | | -121 | | dBc/Hz |
| 1 MHz offset | | | -124 | | dBc/Hz |
| 6 MHz offset | | | -142 | | dBc/Hz |
| 10 MHz offset | | | -146 | | dBc/Hz |
| 40 MHz offset | | | -155 | | dBc/Hz |
| VCO sensitivity (Kv) | | | 72 | | MHz/V |
| SYNTHESIZER SPECIFICATIONS | | | | | |
| fLO = 1.710 GHz, fVCO2 = 3.420 GHz | Measured at LO output, LO_DIV_A = 01 | | | | |
| fPFD Spurs | fREF = 153.6 MHz, fPFD = 38.4 MHz, 120 kHz loop filter | | | | |
| | fPFD × 1 | | -83 | | dBc |
| | fPFD × 2 | | -89 | | dBc |
| | fPFD × 3 | | -90 | | dBc |
| | fPFD × 4 | | -93 | | dBc |
| Closed-Loop Phase Noise | 1 kHz offset | | -97 | | dBc/Hz |
| | 10 kHz offset | | -110 | | dBc/Hz |
| | 100 kHz offset | | -107 | | dBc/Hz |
| | 800 kHz offset | | -128 | | dBc/Hz |
| | 1 MHz offset | | -132 | | dBc/Hz |
| | 6 MHz offset | | -144 | | dBc/Hz |
| | 10 MHz offset | | -152 | | dBc/Hz |
| Integrated Phase Noise | 40 MHz offset | | -158 | | dBc/Hz |
| | 10 kHz to 40 MHz integration bandwidth | | 0.21 | | ° rms |
| | Figure of Merit (FOM) ¹ | | -222 | | dBc/Hz |

| Parameter | Test Conditions/Comments | Min | Typ | Max | Unit |
|--|--|-----|------|-----|--------|
| $f_{LO} = 2.305 \text{ GHz}$, $f_{VCO1} = 4.610 \text{ GHz}$ f_{PFD} Spurs | $f_{PFD} \times 1$ | | -84 | | dBc |
| | $f_{PFD} \times 2$ | | -87 | | dBc |
| | $f_{PFD} \times 3$ | | -91 | | dBc |
| | $f_{PFD} \times 4$ | | -92 | | dBc |
| Closed-Loop Phase Noise | 1 kHz offset | | -93 | | dBc/Hz |
| | 10 kHz offset | | 105 | | dBc/Hz |
| | 100 kHz offset | | -103 | | dBc/Hz |
| | 800 kHz offset | | -116 | | dBc/Hz |
| | 1 MHz offset | | -130 | | dBc/Hz |
| | 6 MHz offset | | -144 | | dBc/Hz |
| | 10 MHz offset | | -152 | | dBc/Hz |
| | 40 MHz offset | | -156 | | dBc/Hz |
| Integrated Phase Noise Figure of Merit ¹ | 10 kHz to 40 MHz integration bandwidth | | 0.3 | | ° rms |
| | | | -222 | | dBc/Hz |
| $f_{LO} = 2.75 \text{ GHz}$, $f_{VCO2} = 5.5 \text{ GHz}$ f_{PFD} Spurs | $f_{PFD} \times 1$ | | -82 | | dBc |
| | $f_{PFD} \times 2$ | | -88 | | dBc |
| | $f_{PFD} \times 3$ | | -93 | | dBc |
| | $f_{PFD} \times 4$ | | -96 | | dBc |
| Closed-Loop Phase Noise | 1 kHz offset | | -93 | | dBc/Hz |
| | 10 kHz offset | | -101 | | dBc/Hz |
| | 100 kHz offset | | -99 | | dBc/Hz |
| | 800 kHz offset | | -122 | | dBc/Hz |
| | 1 MHz offset | | -128 | | dBc/Hz |
| | 6 MHz offset | | -144 | | dBc/Hz |
| | 10 MHz offset | | -151 | | dBc/Hz |
| | 40 MHz offset | | -154 | | dBc/Hz |
| Integrated Phase Noise Figure of Merit ¹ | 10 kHz to 40 MHz integration bandwidth | | 0.38 | | ° rms |
| | | | -222 | | dBc/Hz |

¹ Figure of merit (FOM) is computed as phase noise (dBc/Hz) - 10 log 10(f_{PFD}) - 20 log 10(f_{LO}/f_{PFD}). The FOM was measured across the full LO range, with $f_{REF} = 160 \text{ MHz}$ and f_{REF} power = 4 dBm (500 V/ μs slew rate) with a 40 MHz f_{PFD} . The FOM was computed at 50 kHz offset.

RF INPUT TO MIXER OUTPUT SPECIFICATIONS

VCCX = 5 V, TA = 25°C, high-side LO injection, f_{IF} = 200 MHz, external LO frequency, and RF attenuation = 0 dB, unless otherwise noted. Mixer settings configured for maximum linearity (see Table 16). All losses from input and output traces and baluns are de-embedded from results.

Table 4. RF Switch + Balun + RF Attenuator + Mixer

| Parameter | Test Conditions/Comments | Min | Typ | Max | Unit |
|---|--|-----|------|-----|------|
| VOLTAGE GAIN | Differential 255 Ω load | | -4 | | dB |
| MIXER OUTPUT IMPEDANCE | Differential (see Figure 87) | | 255 | | Ω |
| DYNAMIC PERFORMANCE AT f _{RF} = 900 MHz | | | | | |
| Voltage Conversion Gain | | | -2 | | dB |
| Input P1dB | | | 17 | | dBm |
| Input IP3 | -5 dBm each input tone, 1 MHz tone spacing | | 40 | | dBm |
| Input IP2 | -5 dBm each input tone, 1 MHz tone spacing | | 65 | | dBm |
| Noise Figure | | | 15 | | dB |
| LO to RF Leakage | | | -70 | | dBm |
| RF to LO Leakage | | | -60 | | dBc |
| LO to IF Leakage | | | -32 | | dBm |
| RF to IF Leakage | With respect to 0 dBm RF input power | | -45 | | dBc |
| Isolation ¹ | Isolation between RFIN0 and RFIN3 | | -52 | | dBc |
| DYNAMIC PERFORMANCE AT f _{RF} = 1900 MHz | | | | | |
| Voltage Conversion Gain | | | -3 | | dB |
| Input P1dB | | | 17 | | dBm |
| Input IP3 | -5 dBm each input tone, 1 MHz tone spacing | | 40 | | dBm |
| Input IP2 | -5 dBm each input tone, 1 MHz tone spacing | | 62 | | dBm |
| Noise Figure | | | 17 | | dB |
| LO to RF Leakage | | | -60 | | dBm |
| RF to LO Leakage | | | -50 | | dBc |
| LO to IF Leakage | | | -35 | | dBm |
| RF to IF Leakage | With respect to 0 dBm RF input power | | -43 | | dBc |
| Isolation ¹ | Isolation between RFIN0 and RFIN3 | | -47 | | dBc |
| DYNAMIC PERFORMANCE AT f _{RF} = 2100 MHz | | | | | |
| Voltage Conversion Gain | | | -3.5 | | dB |
| Input P1dB | | | 18 | | dBm |
| Input IP3 | -5 dBm each input tone, 1 MHz tone spacing | | 40 | | dBm |
| Input IP2 | -5 dBm each input tone, 1 MHz tone spacing | | 54.5 | | dBm |
| Noise Figure | | | 18 | | dB |
| LO to RF Leakage | | | -60 | | dBm |
| RF to LO Leakage | | | -40 | | dBc |
| LO to IF Leakage | | | -35 | | dBm |
| RF to IF Leakage | With respect to 0 dBm RF input power | | -40 | | dBc |
| Isolation ¹ | Isolation between RFIN0 and RFIN3 | | -45 | | dBc |
| DYNAMIC PERFORMANCE AT f _{RF} = 2700 MHz | | | | | |
| Voltage Conversion Gain | | | -4.7 | | dB |
| Input P1dB | | | 19 | | dBm |
| Input IP3 | -5 dBm each input tone, 1 MHz tone spacing | | 40 | | dBm |
| Input IP2 | -5 dBm each input tone, 1 MHz tone spacing | | 56 | | dBm |
| Noise Figure | | | 21 | | dB |
| LO to RF Leakage | | | -60 | | dBm |
| RF to LO Leakage | | | -45 | | dBc |
| LO to IF Leakage | | | -40 | | dBm |
| RF to IF Leakage | With respect to 0 dBm RF input power | | -42 | | dBc |
| Isolation ¹ | Isolation between RFIN0 and RFIN3 | | -41 | | dBc |

¹ Isolation between RF inputs. An input signal was applied to RFIN0 while RFIN1 to RFIN3 were terminated with 50 Ω. The IF signal amplitude was measured at the mixer output. The internal switch was then configured for RFIN3, and the feedthrough was measured as a delta from the fundamental.

IF DGA SPECIFICATIONS

$V_{CCX} = 5\text{ V}$, $T_A = 25^\circ\text{C}$, $R_S = R_L = 150\ \Omega$ differential, $f_{IF} = 200\text{ MHz}$, 2 V p-p differential output, unless otherwise noted. All losses from input and output traces and baluns are de-embedded from results.

Table 5.

| Parameter | Test Conditions/Comments | Min | Typ | Max | Unit |
|--|--|-----|-----------|-----|----------|
| BANDWIDTH | | | | | |
| -1 dB Bandwidth | $V_{OUT} = 2\text{ V p-p}$ | | 500 | | MHz |
| -3 dB Bandwidth | $V_{OUT} = 2\text{ V p-p}$ | | 700 | | MHz |
| SLEW RATE | | | 5.5 | | V/ns |
| INPUT STAGE | | | | | |
| Input P1dB | At minimum gain | | 17 | | dBm |
| Input Impedance | | | 150 | | Ω |
| Common-Mode Input Voltage | | | 1.5 | | V |
| Common-Mode Rejection Ratio (CMRR) | | | 50 | | dB |
| GAIN | | | | | |
| Power/Voltage Gain, Step Size = 0.5 dB | | 3 | | 15 | dB |
| Gain Flatness | $50\text{ MHz} < f_c < 200\text{ MHz}$ | | 0.2 | | dB |
| Gain Conformance Error | | | ± 0.1 | | dB |
| Gain Temperature Sensitivity | | | 0.008 | | dB/C |
| Gain Step Response | | | 15 | | ns |
| OUTPUT STAGE | | | | | |
| Output P1dB | | | 18 | | dBm |
| Output Impedance | See Figure 88 | | 150 | | Ω |
| NOISE/HARMONIC PERFORMANCE at 200 MHz | | | | | |
| Output IP3 | 1 V p-p each output tone, 1 MHz tone spacing | | 45 | | dBm |
| Output IP2 | 1 V p-p each output tone, 1 MHz tone spacing | | 63 | | dBm |
| HD2 | $V_{OUT} = 2\text{ V p-p}$ | | -87 | | dBc |
| HD3 | $V_{OUT} = 2\text{ V p-p}$ | | -84 | | dBc |
| Noise Figure | | | 10 | | dB |

DIGITAL LOGIC SPECIFICATIONS

Table 6.

| Parameter | Symbol | Test Conditions/Comments | Min | Typ | Max | Unit |
|---|--------------|--------------------------|-----|-----|------|------|
| SERIAL PORT INTERFACE TIMING | | | | | | |
| Input Voltage High | V_{IH} | | 1.4 | | | V |
| Input Voltage Low | V_{IL} | | | | 0.70 | V |
| Output Voltage High | V_{OH} | $I_{OH} = -100 \mu A$ | 2.3 | | | V |
| Output Voltage Low | V_{OL} | $I_{OL} = +100 \mu A$ | 0.2 | | | V |
| Serial Clock Period | t_{SCLK} | | 38 | | | ns |
| Setup Time Between Data and Rising Edge of SCLK | t_{DS} | | 8 | | | ns |
| Hold Time Between Data and Rising Edge of SCLK | t_{DH} | | 8 | | | ns |
| Setup Time Between Falling Edge of \overline{CS} and SCLK | t_s | | 10 | | | ns |
| Hold Time Between Rising Edge of \overline{CS} and SCLK | t_H | | 10 | | | ns |
| Minimum Period SCLK Can Be in Logic High State | t_{HIGH} | | 10 | | | ns |
| Minimum Period SCLK Can Be in Logic Low State | t_{LOW} | | 10 | | | ns |
| Maximum Time Delay Between Falling Edge of SCLK and Output Data Valid for a Read Operation | t_{ACCESS} | | | | 231 | ns |
| Maximum Time Delay Between \overline{CS} Deactivation and SDIO Bus Return to High Impedance | t_z | | | | 5 | ns |

Timing Diagram

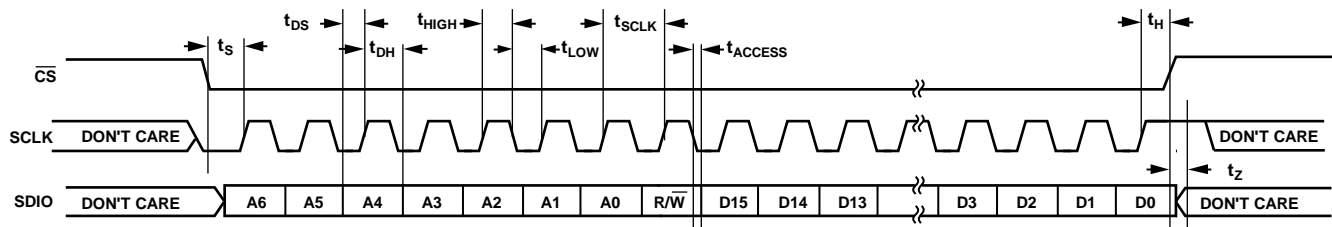


Figure 2. Serial Port Interface Timing

1148E-002

ABSOLUTE MAXIMUM RATINGS

Table 7.

| Parameter | Rating |
|------------------------------|------------------|
| VCCx | -0.5 V to +5.5 V |
| RFSW0, RFSW1 | -0.3 V to +3.6 V |
| RFIN0, RFIN1, RFIN2, RFIN3 | 20 dBm |
| LOIN-, LOIN+ | 16 dBm |
| REFIN | -0.3 V to +3.6 V |
| IFIN-, IFIN+ | -1.2 V to +3.6 V |
| \overline{CS} , SCLK, SDIO | -0.3 V to +3.6 V |
| VTUNE | -0.3 V to +3.6 V |
| Operating Temperature Range | -40°C to +85°C |
| Storage Temperature Range | -65°C to +150°C |
| Maximum Junction Temperature | 150°C |

Stresses above those listed under Absolute Maximum Ratings may cause permanent damage to the device. This is a stress rating only; functional operation of the device at these or any other conditions above those indicated in the operational section of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

THERMAL RESISTANCE

Table 8. Thermal Resistance

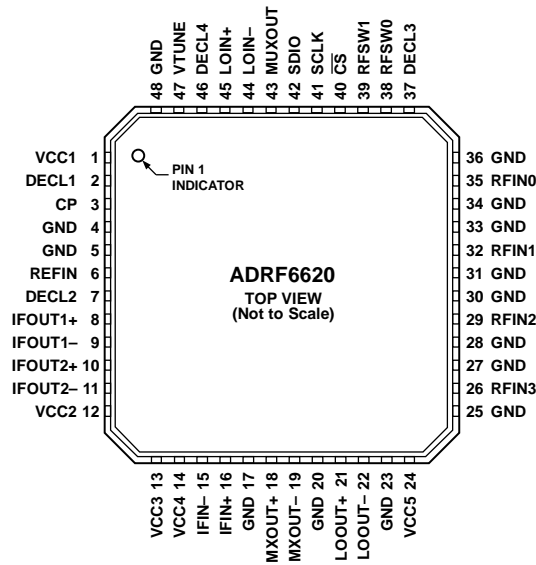
| Package Type | θ_{JC} | Unit |
|---------------|---------------|------|
| 48-Lead LFCSP | 1.62 | °C/W |

ESD CAUTION



ESD (electrostatic discharge) sensitive device. Charged devices and circuit boards can discharge without detection. Although this product features patented or proprietary protection circuitry, damage may occur on devices subjected to high energy ESD. Therefore, proper ESD precautions should be taken to avoid performance degradation or loss of functionality.

PIN CONFIGURATION AND FUNCTION DESCRIPTIONS



NOTES
 1. THE EXPOSED PAD MUST BE CONNECTED TO A GROUND PLANE WITH LOW THERMAL IMPEDANCE.

11489-003

Figure 3. Pin Configuration

Table 9. Pin Function Descriptions¹

| Pin No. | Mnemonic | Description |
|--|------------------------------------|---|
| 1, 12, 13, 14, 24 | VCC1, VCC2, VCC3, VCC4, VCC5 | 5 V Power Supplies. Decouple all power supply pins to ground, using 100 pF and 0.1 μF capacitors. Place the decoupling capacitors near the pins. |
| 2, 7, 37, 46 | DECL1, DECL2, DECL3, DECL4 | Decouple all DECLx pins to ground, using 100 pF, 0.1 μF, and 10 μF capacitors. Place the decoupling capacitors near the pins. |
| 3 | CP | Synthesizer Charge Pump Output. Connect this pin to the VTUNE pin through the loop filter. |
| 4, 5, 17, 20, 23, 25, 27, 28, 30, 31, 33, 34, 36, 48 | GND | Ground. |
| 6 | REFIN | Synthesizer Reference Frequency Input. |
| 8 to 11 | IFOUT1+, IFOUT1-, IFOUT2+, IFOUT2- | IF DGA Outputs. Connect the positive pins such that IFOUT1+ and IFOUT2+ are tied together. Similarly, connect the negative pins such that IFOUT1- and IFOUT2- are tied together. Refer to the Layout section for a recommended layout that minimizes parasitic capacitance and optimizes performance. |
| 15, 16 | IFIN-, IFIN+ | Differential IF DGA Inputs. AC couple the mixer outputs to the IF DGA inputs. |
| 18, 19 | MXOUT+, MXOUT- | Differential Mixer Outputs. AC couple the mixer outputs to the IF DGA inputs. |
| 21, 22 | LOOUT+, LOOUT- | Differential LO Outputs. The differential output impedance is 50 Ω. |
| 26, 29, 32, 35 | RFIN3, RFIN2, RFIN1, RFIN0 | RF Inputs. These single-ended RF inputs have a 50 Ω input impedance and must be ac-coupled. |
| 38, 39 | RFSW0, RFSW1 | External Pin Control of RF Input Switches. For logic high, connect these pins to 2.5 V logic. |
| 40 | CS | SPI Chip Select, Active Low. 3.3 V tolerant logic levels. |
| 41 | SCLK | SPI Clock. 3.3 V tolerant logic levels. |
| 42 | SDIO | SPI Data Input or Output. 3.3 V tolerant logic levels. |
| 43 | MUXOUT | Multiplexer Output. This output pin provides the PLL reference signal or the PLL lock detect signal. |
| 44, 45 | LOIN-, LOIN+ | Differential Local Oscillator Inputs. The differential input impedance is 50 Ω. |
| 47 | VTUNE | VCO Tuning Voltage. Connect this pin to the CP pin through the loop filter. |
| 49 | EPAD | Exposed Pad. The exposed pad must be connected to a ground plane with low thermal impedance. |

¹ For more connection information about these pins, see Table 14.

TYPICAL PERFORMANCE CHARACTERISTICS

RF INPUT TO DGA OUTPUT SYSTEM PERFORMANCE

VCC_X = 5 V, T_A = 25°C, RFDSA_SEL = 00 (0 dB), RFSW_SEL = 00 (RFIN0), BAL_CIN and BAL_COUT optimized for maximum gain; MIXER_BIAS, MIXER_RDAC, and MIXER_CDAC optimized for highest linearity, DGA at maximum gain; third-order low-pass filter between the mixer output and IF DGA input; high-side LO, internal LO frequency, IF frequency = 200 MHz, unless otherwise noted. All losses from input and output traces and baluns are de-embedded from results.

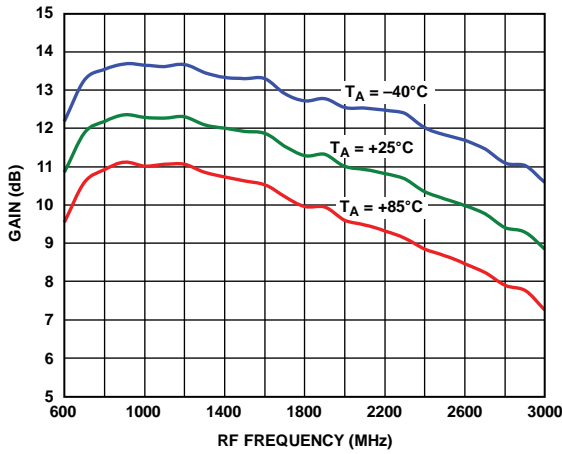


Figure 4. Gain vs. RF Frequency; IF Frequency = 200 MHz

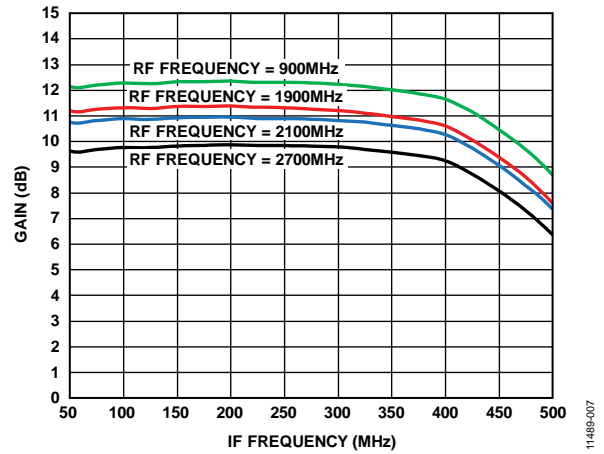


Figure 6. Gain vs. IF Frequency; LO Sweep with Fixed RF, IF Roll-Off

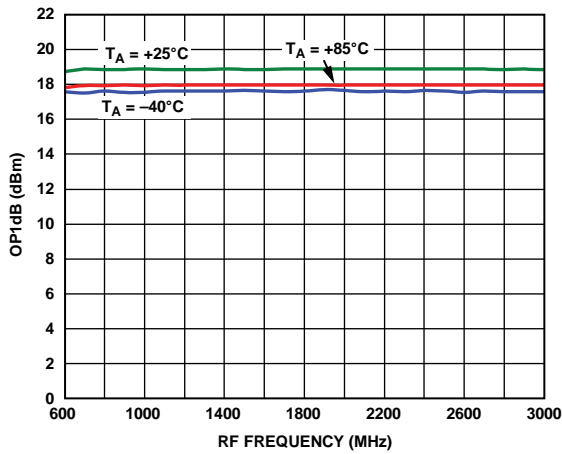


Figure 5. OP1dB vs. RF Frequency

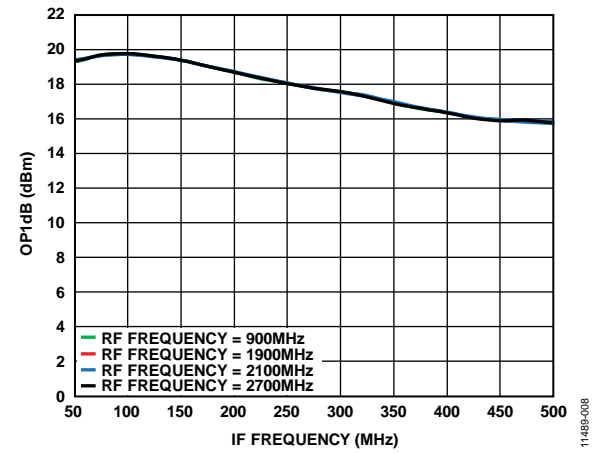


Figure 7. OP1dB vs. IF Frequency; LO Sweep with Fixed RF, IF Roll-Off

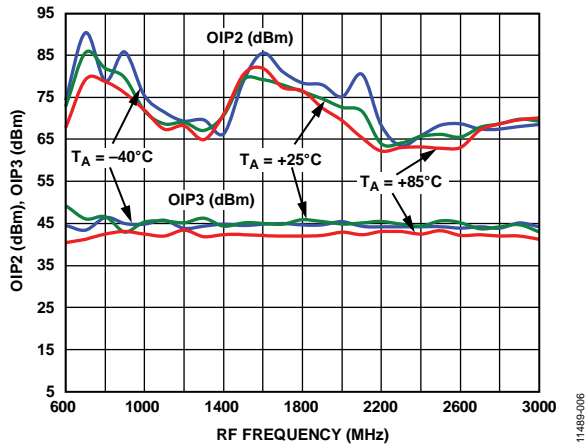


Figure 8. OIP2/OIP3 vs. RF Frequency; Measured on 1 V p-p on Each Tone at DGA Output

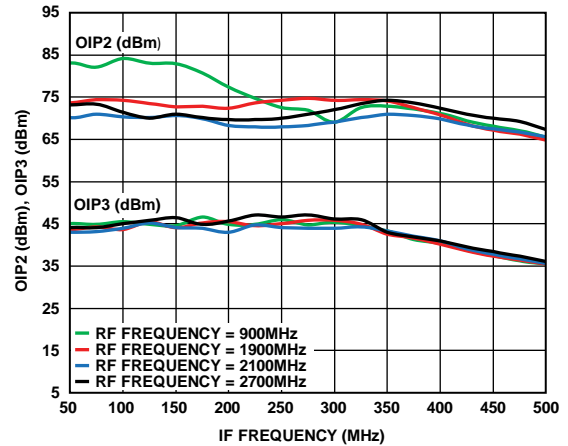


Figure 11. OIP2/OIP3 vs. IF Frequency; LO Sweep with Fixed RF, IF Roll-Off; Measured on 1 V p-p on Each Tone at DGA Output

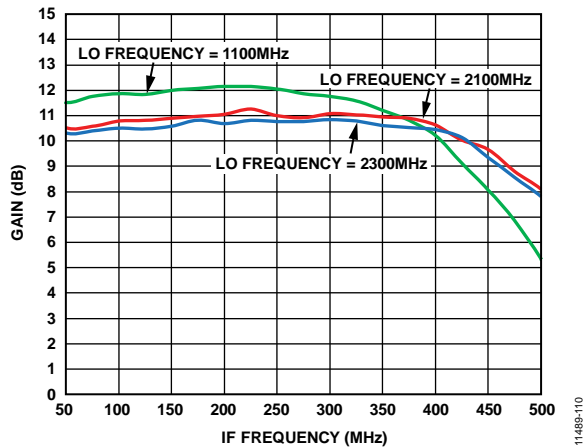


Figure 9. Gain vs. IF Frequency; RF Sweep with Fixed LO; IF and RF Roll-Off; Measured on 1 V p-p on Each Tone at DGA Output

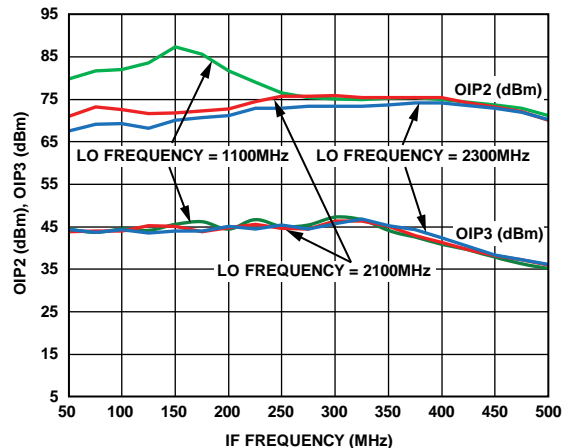


Figure 12. OIP2/OIP3 vs. IF Frequency; RF Sweep with Fixed LO; IF and RF Roll-Off; Measured on 1 V p-p on Each Tone at DGA Output

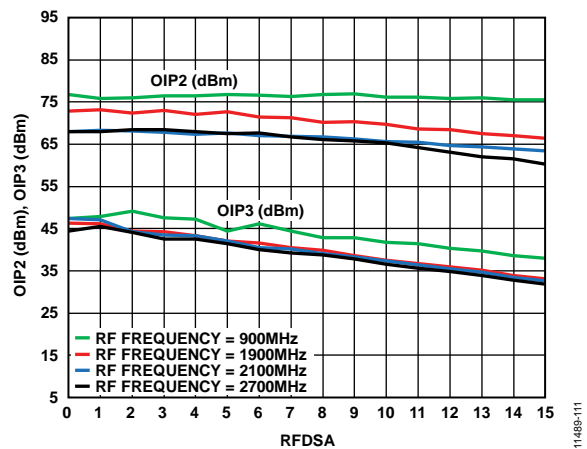


Figure 10. OIP2/OIP3 vs. RFDSA; Measured on 1 V p-p on Each Tone at DGA Output

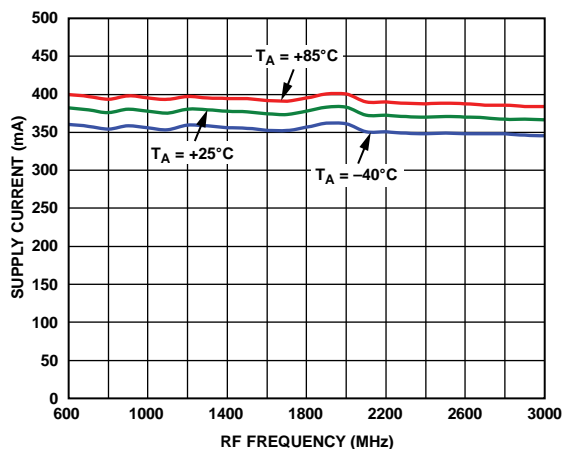


Figure 13. Supply Current vs. RF Frequency

PHASE-LOCKED LOOP (PLL)

VCCX = 5 V, TA = 25°C, 120 kHz loop filter, fREF = 153.6 MHz, PLL reference amplitude = 4 dBm, fFPD = 38.4 MHz, measured at LO output, unless otherwise noted.

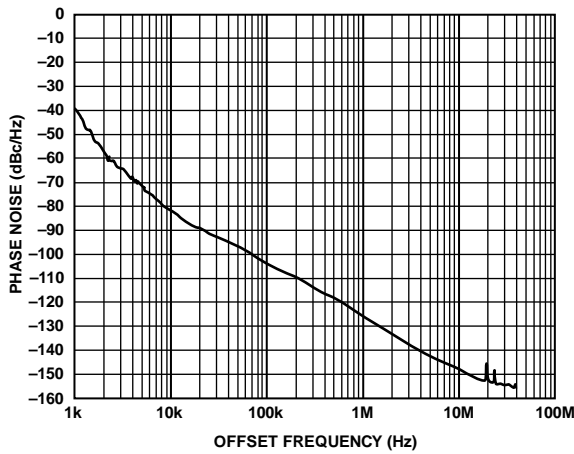


Figure 14. VCO2 Open-Loop VCO Phase Noise vs. Offset Frequency; $f_{VCO2} = 3.4$ GHz, LO_DIV_A = 00, VTUNE = 2 V

11489-010

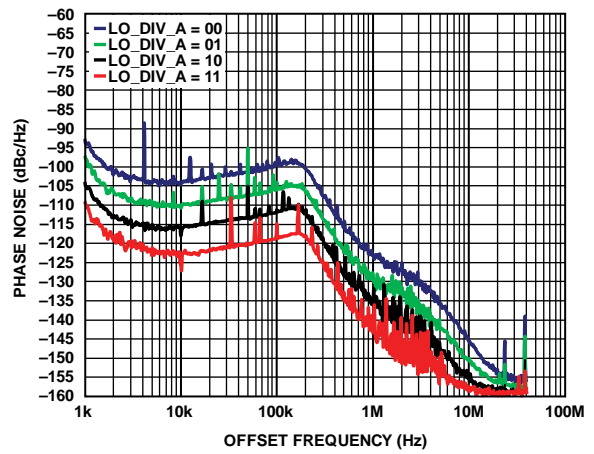


Figure 17. VCO2 Closed-Loop Phase Noise for Various LO_DIV_A Dividers vs. Offset Frequency; $f_{VCO2} = 3.4$ GHz

11489-013

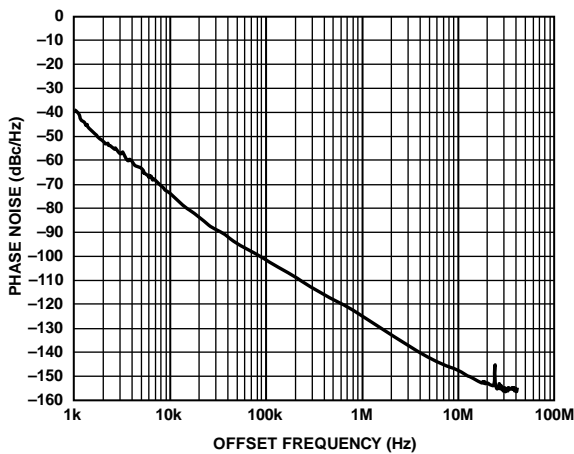


Figure 15. VCO1 Open-Loop Phase Noise vs. Offset Frequency; $f_{VCO1} = 4.6$ GHz, LO_DIV_A = 00, VTUNE = 2 V

11489-011

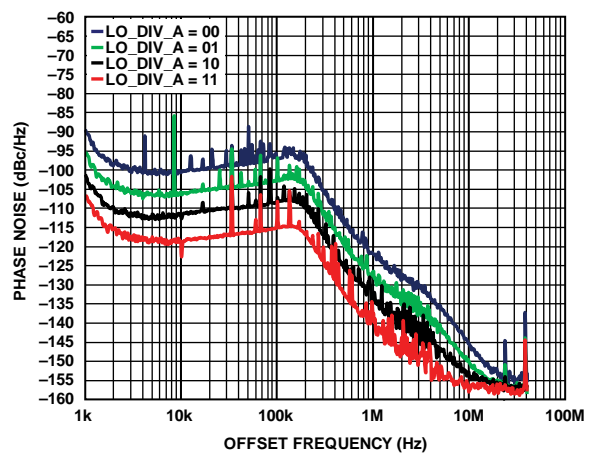


Figure 18. VCO1 Closed-Loop Phase Noise for Various LO_DIV_A Dividers vs. Offset Frequency; $f_{VCO1} = 4.6$ GHz

11489-014

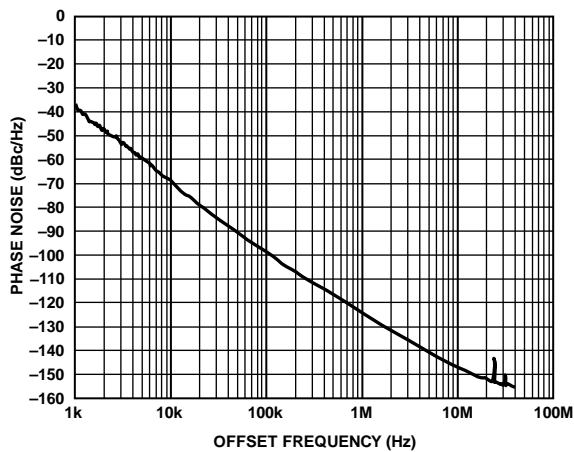


Figure 16. VCO0 Open-Loop Phase Noise vs. Offset Frequency; $f_{VCO0} = 5.5$ GHz, LO_DIV_A = 00, VTUNE = 2 V

11489-012

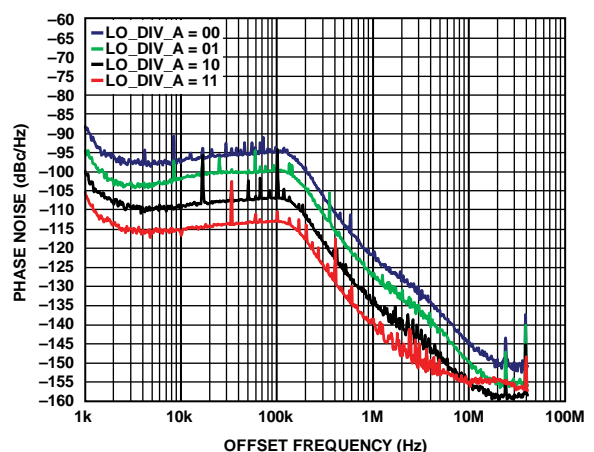


Figure 19. VCO0 Closed-Loop Phase Noise for Various LO_DIV_A Dividers vs. Offset Frequency; $f_{VCO0} = 5.532$ GHz

11489-015

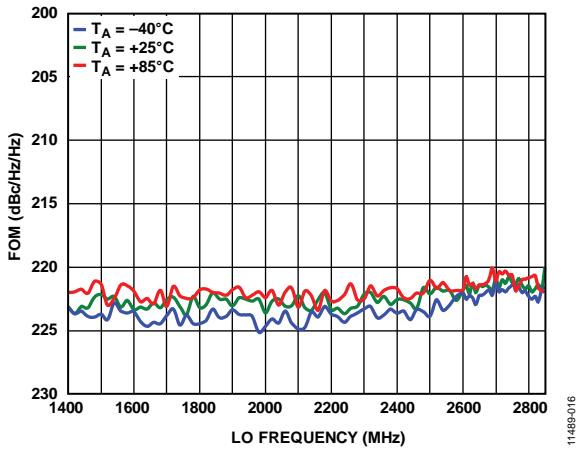


Figure 20. PLL Figure of Merit (FOM) vs. LO Frequency

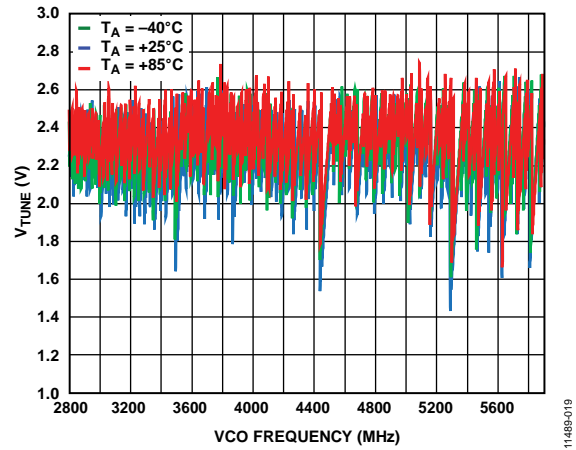


Figure 23. V_{TUNE} vs. VCO Frequency

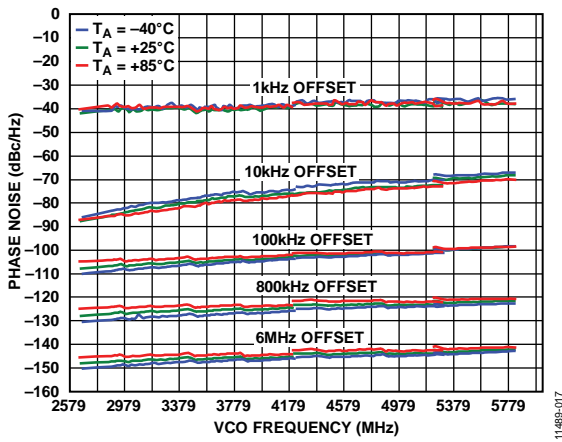


Figure 21. Open-Loop Phase Noise vs. VCO Frequency; $LO_DIV_A = 00$

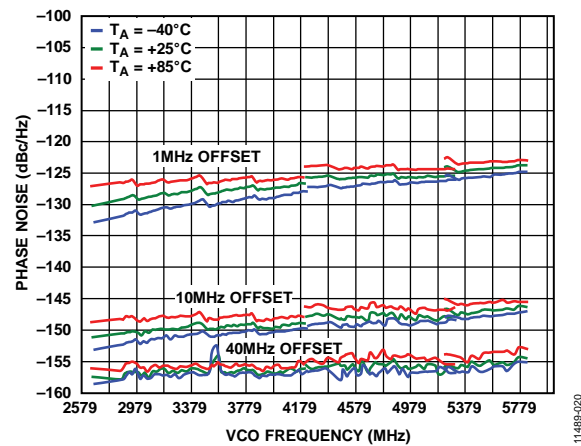


Figure 24. Open-Loop Phase Noise vs. VCO Frequency; $LO_DIV_A = 00$

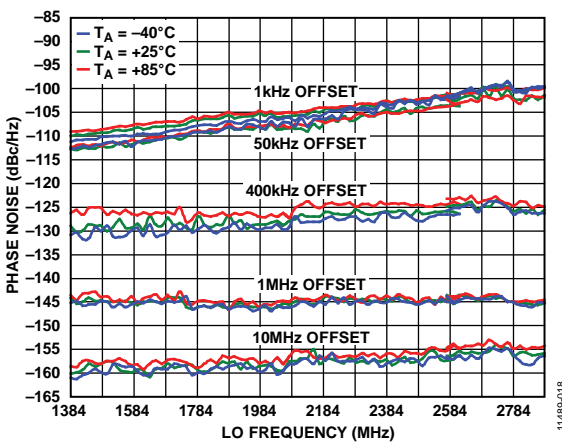


Figure 22. 120 kHz Bandwidth Loop Phase Noise, $LO_DIV_A = 01$; Offset = 1 kHz, 50 kHz, 400 kHz, 1 MHz, and 10 MHz

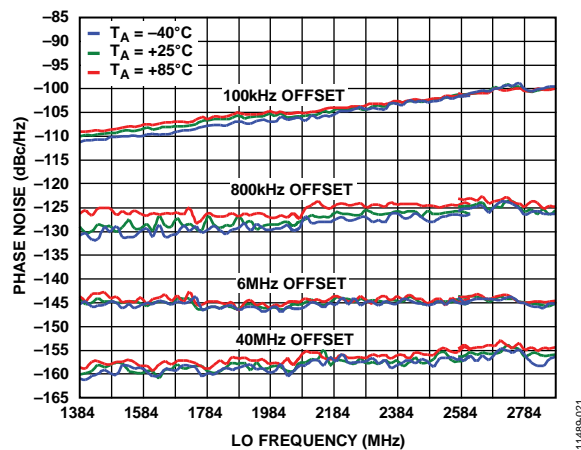


Figure 25. 120 kHz Bandwidth Loop Phase Noise, $LO_DIV_A = 01$; Offset = 100 kHz, 800 kHz, 6 MHz, and 40 MHz

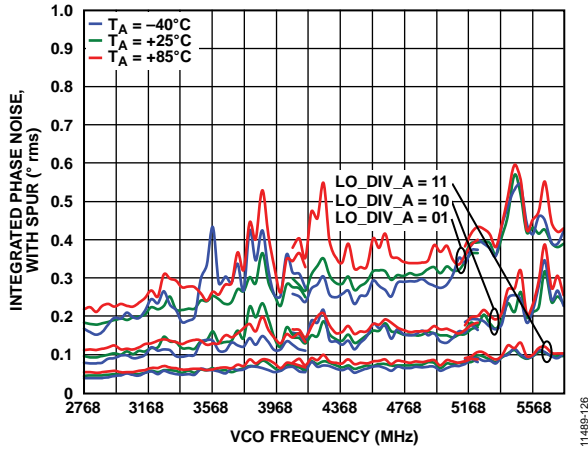


Figure 26. 10 kHz to 40 MHz Integrated Phase Noise vs. VCO Frequency; LO_DIV_A = 01, 10, and 11, Including Spurs, for Various LO Divider Ratios

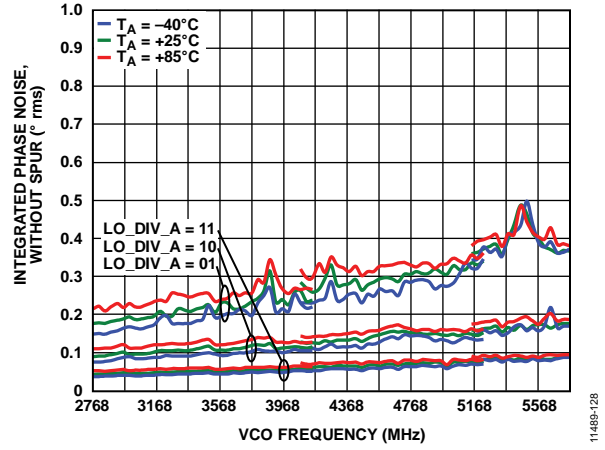


Figure 29. 10 kHz to 40 MHz Integrated Phase Noise vs. VCO Frequency; LO_DIV_A = 01, 10, and 11, Excluding Spurs, for Various LO Divider Ratios

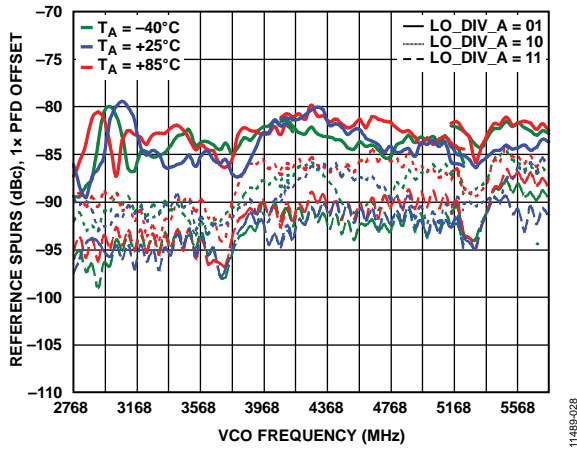


Figure 27. f_{PFD} Spurs vs. VCO Frequency; 1x PFD Offset; Measured at LO Output

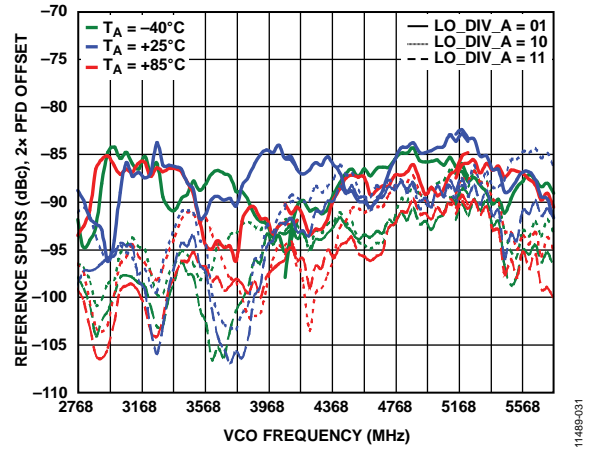


Figure 30. f_{PFD} Spurs vs. VCO Frequency; 2x PFD Offset; Measured at LO Output

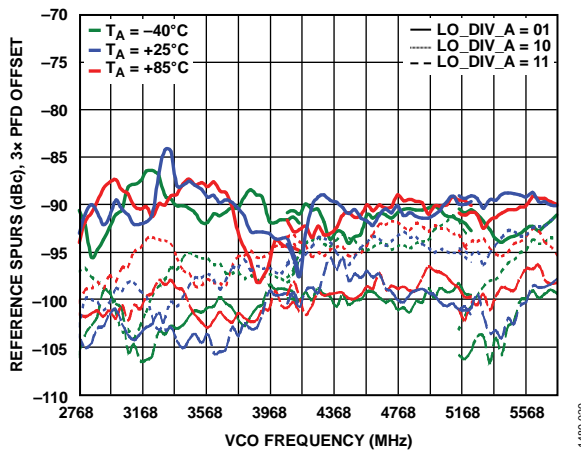


Figure 28. f_{PFD} Spurs vs. VCO Frequency; 3x PFD Offset; Measured at LO Output

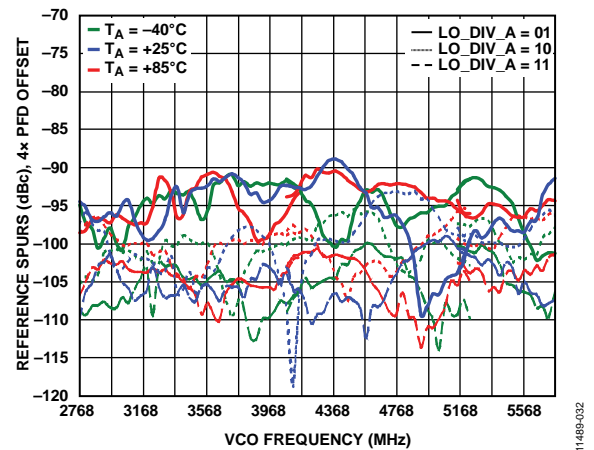


Figure 31. f_{PFD} Spurs vs. VCO Frequency; 4x PFD Offset; Measured at LO Output

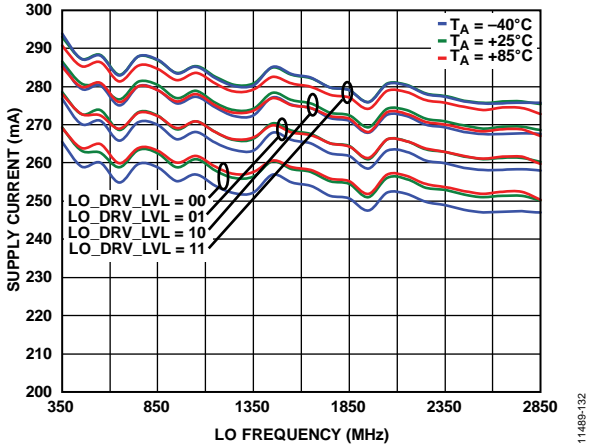


Figure 32. Supply Current vs. LO Frequency; LO_DRV_LVL = 00, 01, 10, and 11

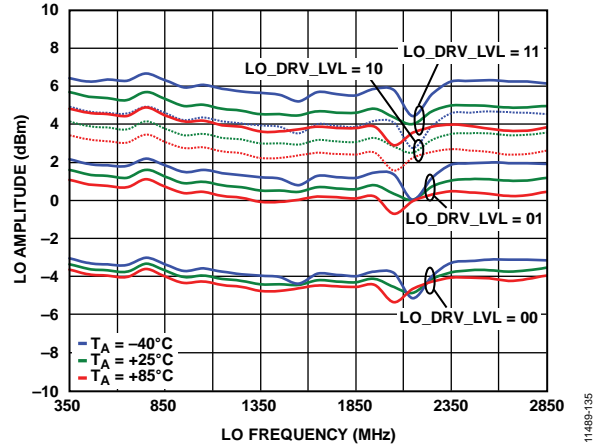


Figure 35. LO Amplitude vs. LO Frequency; LO_DRV_LVL = 00, 01, 10, and 11

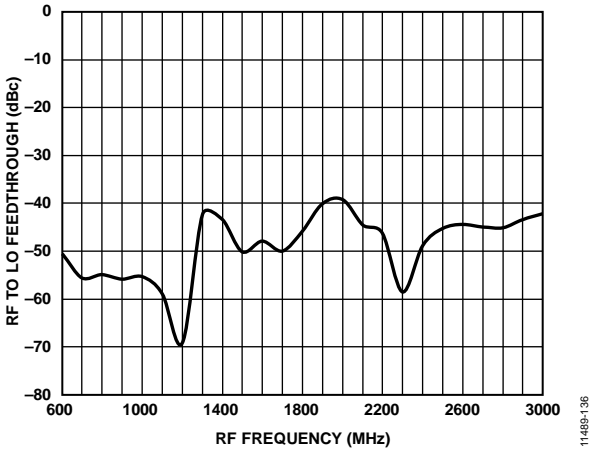


Figure 33. RF to LO Output Feedthrough, LO_DRV_LVL = 00

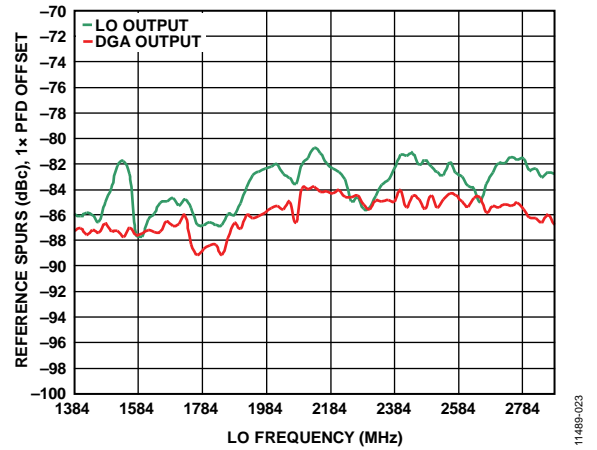


Figure 36. f_{PFD} Spurs, LO_DIV_A = 01, 1x PFD Offset; Measured on LO Output and DGA Output

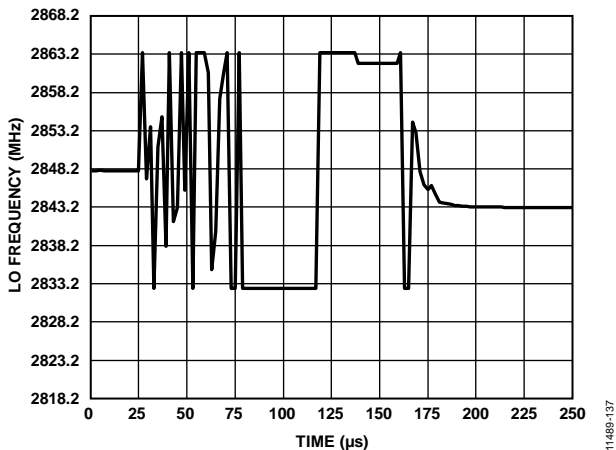


Figure 34. LO Frequency Settling Time, Loop Filter Bandwidth = 120 kHz

RF INPUT TO MIXER OUTPUT PERFORMANCE

VCCX = 5 V, TA = 25°C, RL = 250 Ω, external LO, PLO = 0 dBm, RFDSA_SEL = 00 (0 dB), RFSW_SEL = 00 (RFIN0), BAL_CIN and BAL_COUT optimized, MIXER_BIAS, MIXER_RDAC, and MIXER_CDAC optimized for highest linearity, DGA and LO output disabled, unless otherwise noted. All losses from input and output traces and baluns are de-embedded from results.

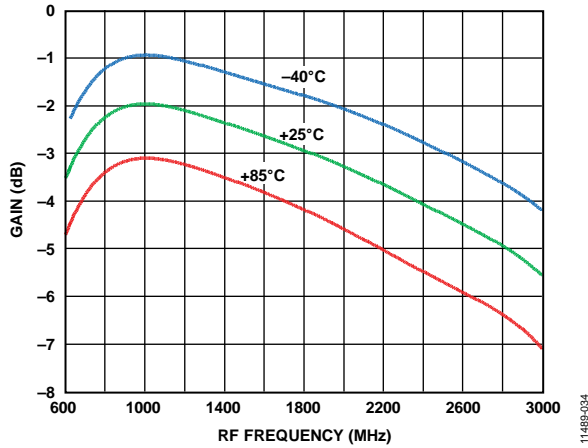


Figure 37. Mixer Gain vs. RF Frequency

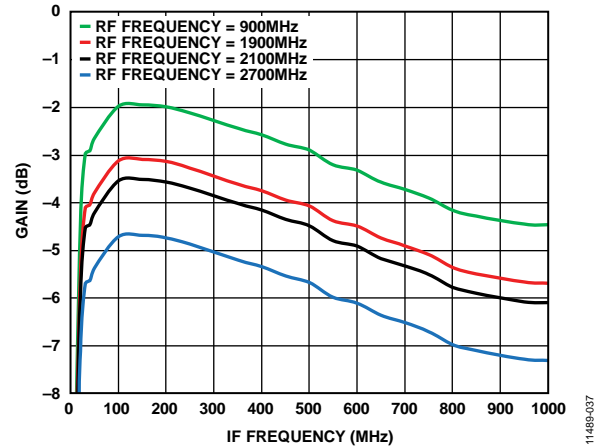


Figure 40. Mixer Gain vs. IF Frequency; LO Sweep with Fixed RF, IF Roll-Off

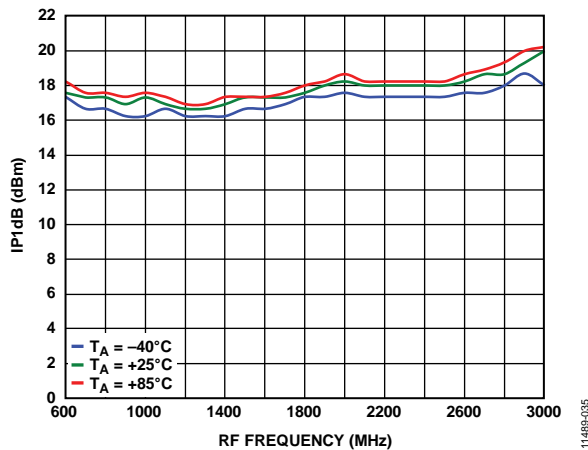


Figure 38. Mixer IP1dB vs. RF Frequency

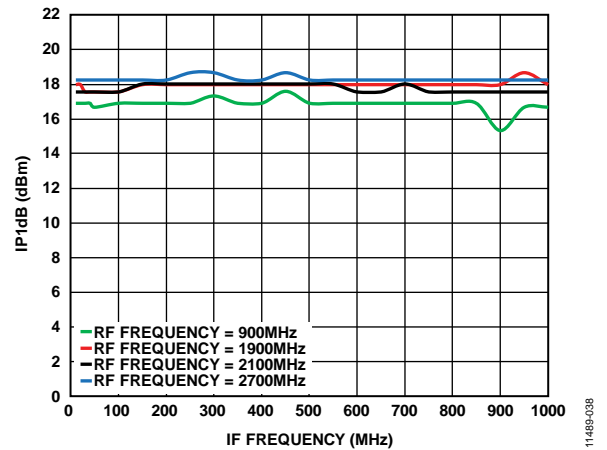


Figure 41. Mixer IP1dB vs. IF Frequency; LO Sweep with Fixed RF, IF Roll-Off

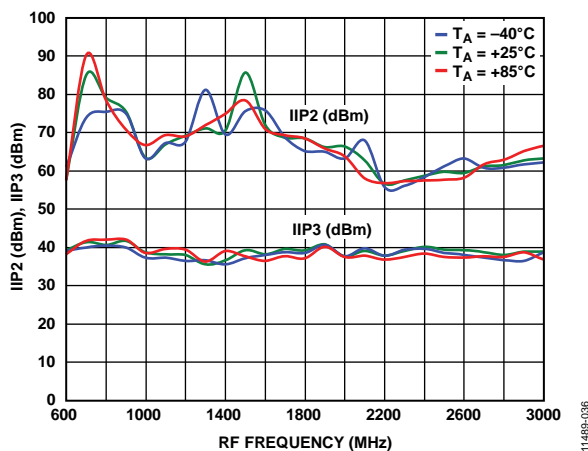


Figure 39. Mixer IIP2/IIP3 vs. RF Frequency; PIN = -5 dBm/Tone, 1 MHz Spacing

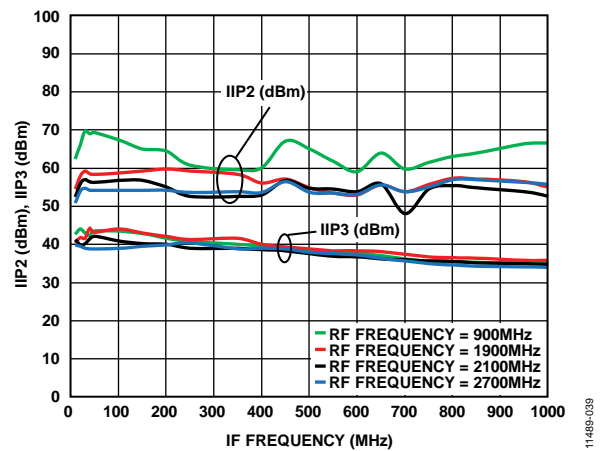


Figure 42. Mixer IIP2/IIP3 vs. IF Frequency; PIN = -5 dBm/Tone, 1 MHz Spacing, LO Sweep with Fixed RF, IF Roll-Off

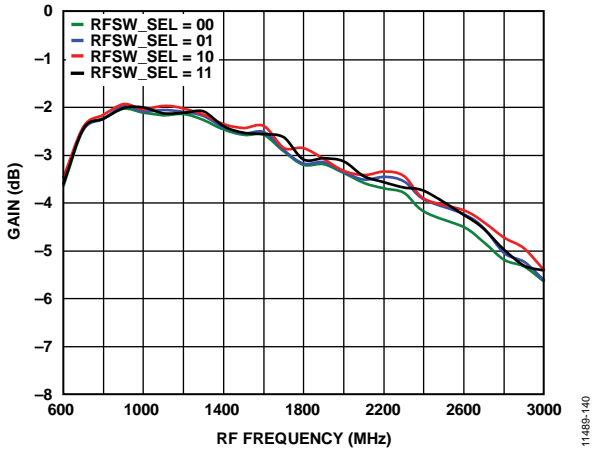


Figure 43. Mixer Gain vs. RF Frequency; RFSW_SEL = 00, 01, 10, and 11

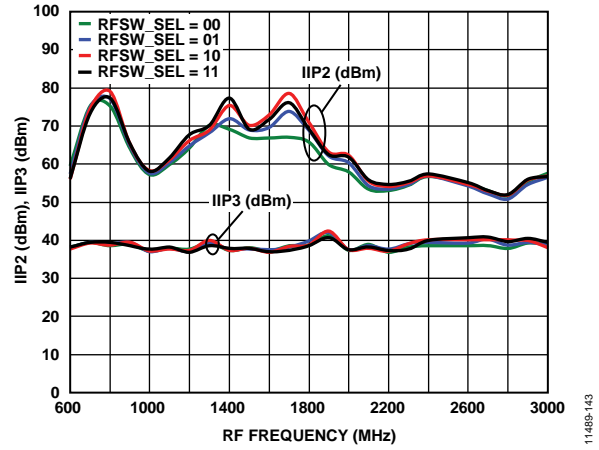


Figure 46. Mixer IIP2/IIP3 vs. RF Frequency; RFSW_SEL = 00, 01, 10, and 11

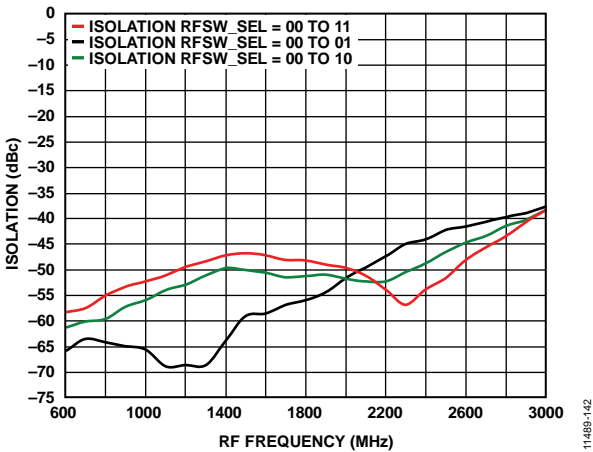


Figure 44. Mixer Input to Mixer Output Isolation vs. RF Frequency; RFSW_SEL = 00 Driven

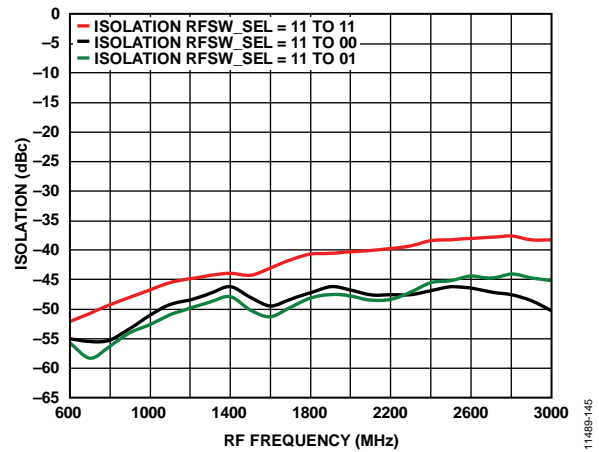


Figure 47. Mixer Input to Mixer Output Isolation vs. RF Frequency; RFSW_SEL = 11 Driven

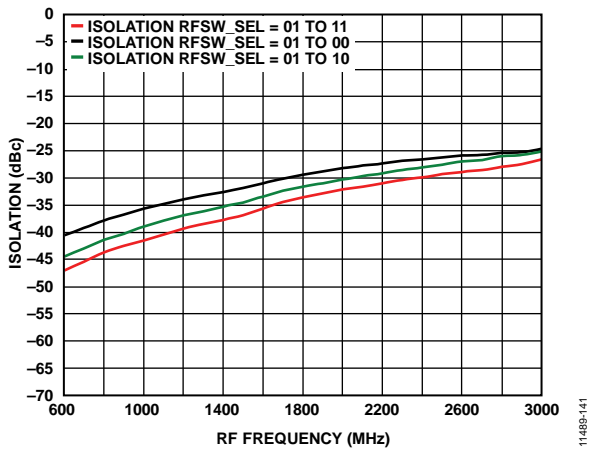


Figure 45. Mixer Input to Mixer Output Isolation vs. RF Frequency; RFSW_SEL = 01 Driven

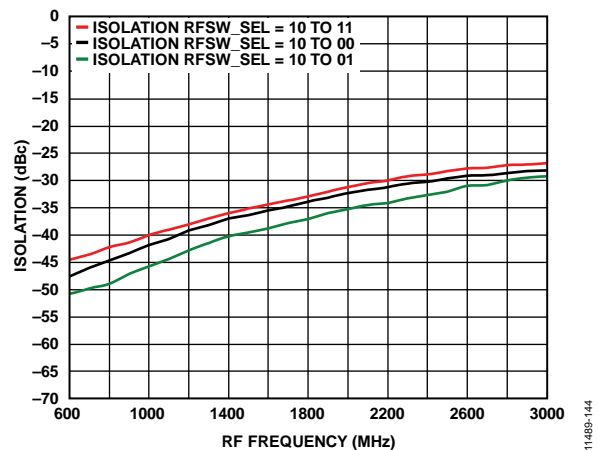


Figure 48. Mixer Input to Mixer Output Isolation vs. RF Frequency; RFSW_SEL = 10 Driven

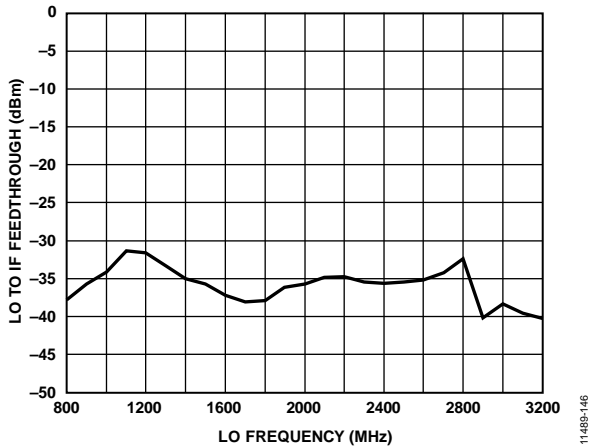


Figure 49. LO to IF Feedthrough at Mixer Output Without Filtering

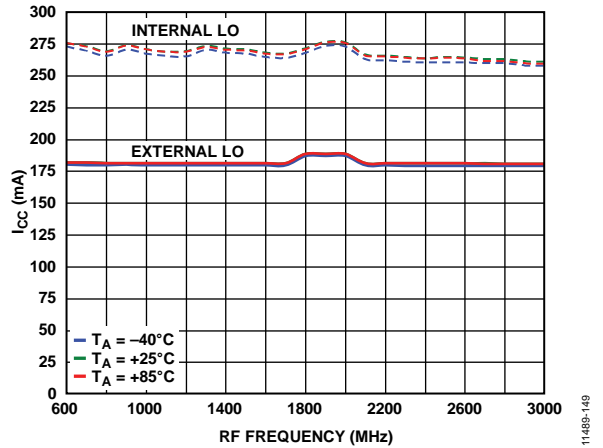


Figure 52. I_{CC} vs. RF Frequency; DGA and LO Output Disabled

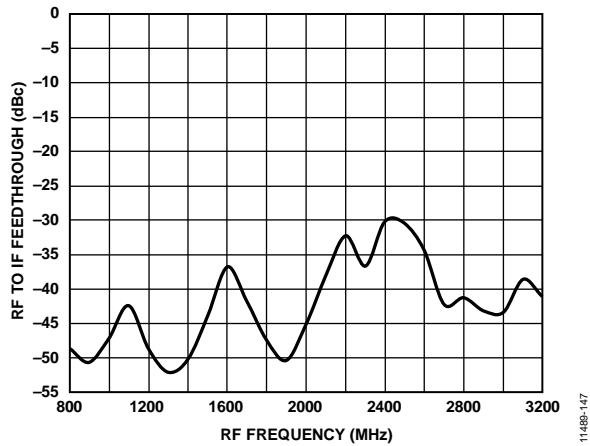


Figure 50. RF to IF Feedthrough at Mixer Output Without Filtering; Mixer Input Power = 0 dBm

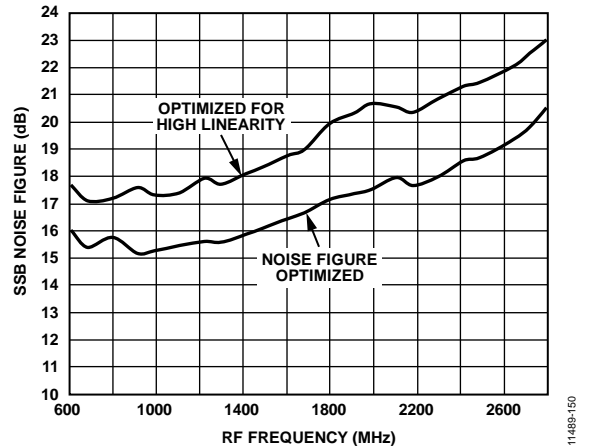


Figure 53. SSB Noise Figure vs. RF Frequency (see Table 16)

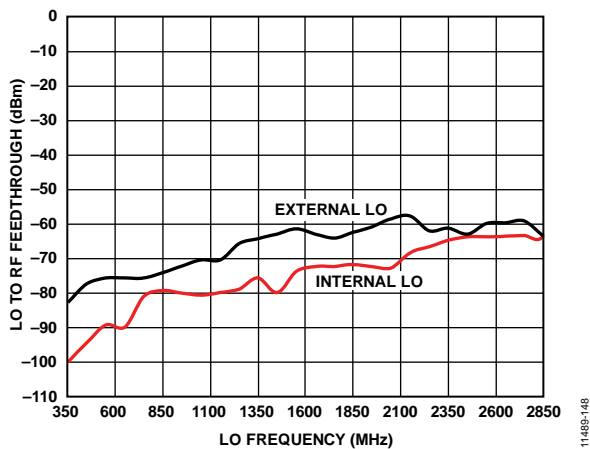


Figure 51. LO to RF Feedthrough; $P_{LO} = 0$ dBm

IF DGA

VCCX = 5 V, TA = 25°C, RS = RL = 150 Ω, IF = 200 MHz, 2 V p-p differential output, unless otherwise noted. All losses from input and output traces and baluns are de-embedded from results.

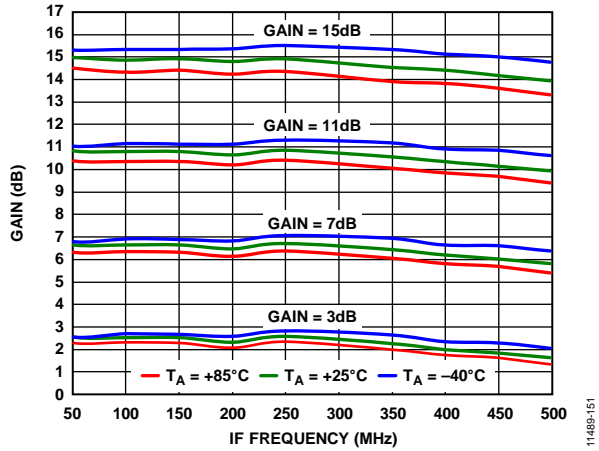


Figure 54. DGA Gain vs. IF Frequency and Temperature

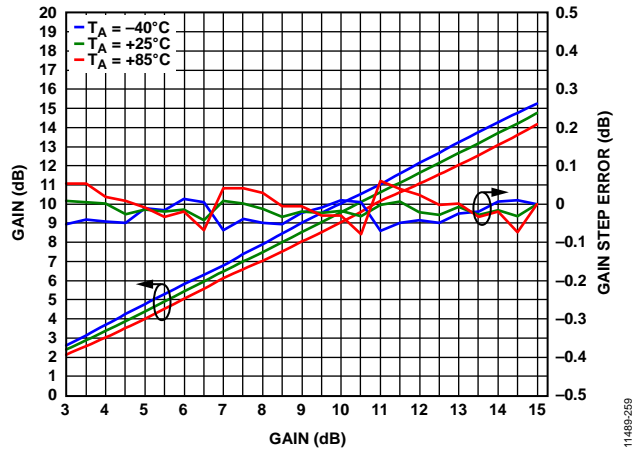


Figure 57. DGA Gain and Gain Step Error vs. Gain Setting and Temperature

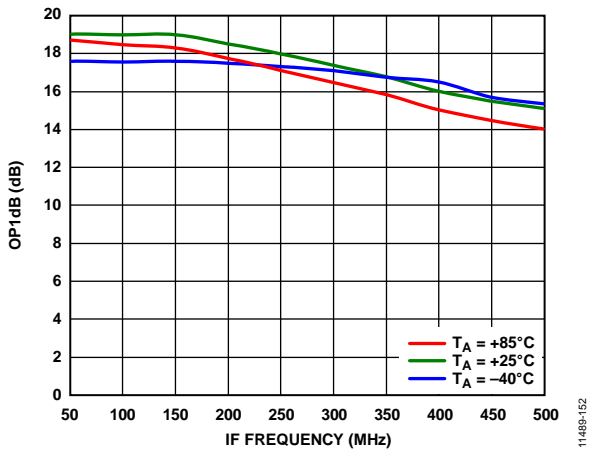


Figure 55. DGA OP1dB vs. Frequency and Temperature; Maximum Gain

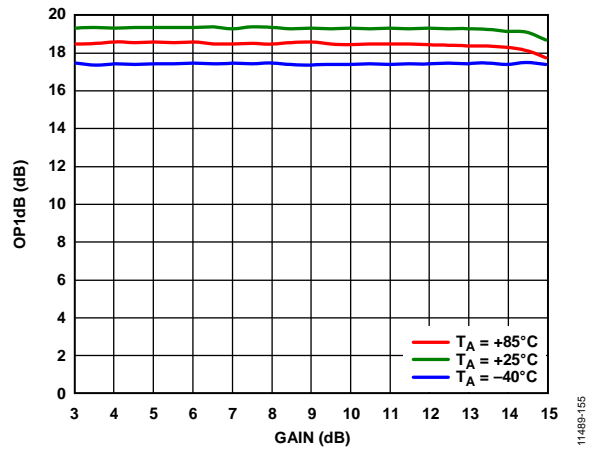


Figure 58. DGA OP1dB vs. Gain Setting and Temperature

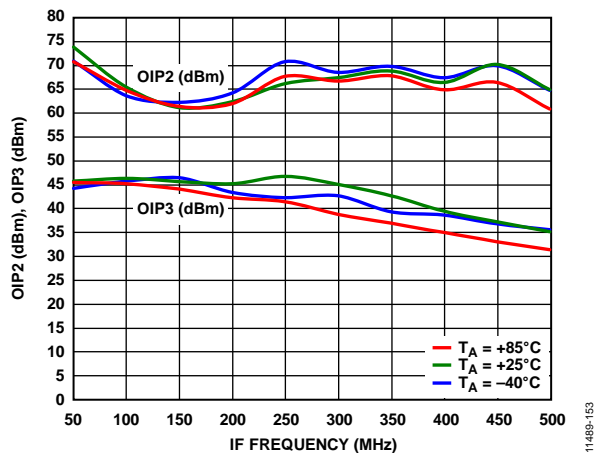


Figure 56. DGA OIP2/OIP3 vs. IF Frequency and Temperature; Maximum Gain

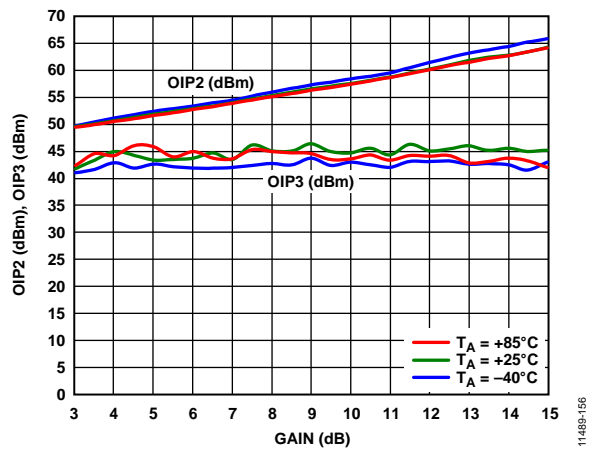


Figure 59. DGA OIP2/OIP3 vs. Gain Setting and Temperature

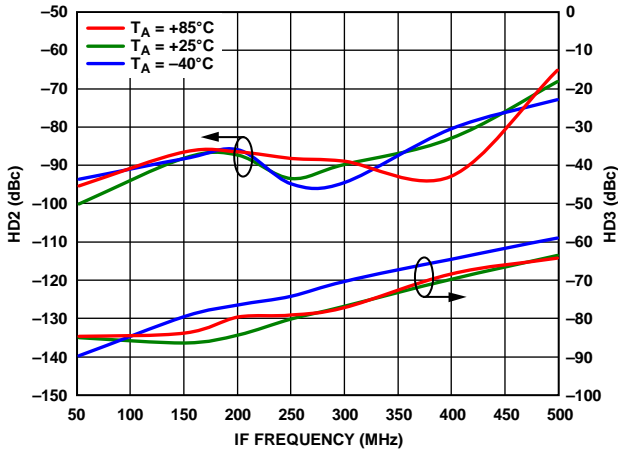


Figure 60. DGA HD2/HD3 vs. IF Frequency and Temperature; Maximum Gain

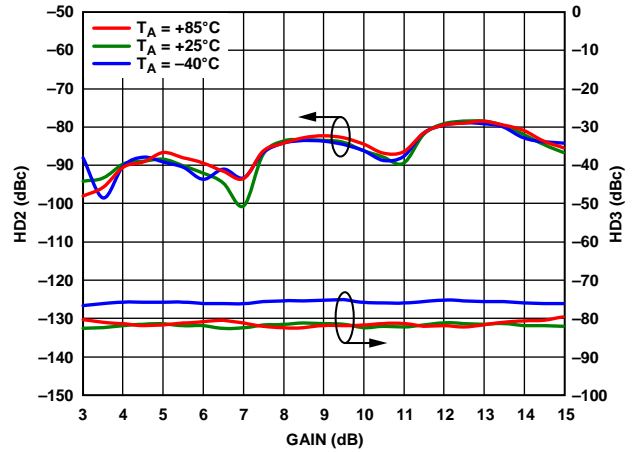


Figure 63. DGA HD2/HD3 vs. Gain Setting and Temperature

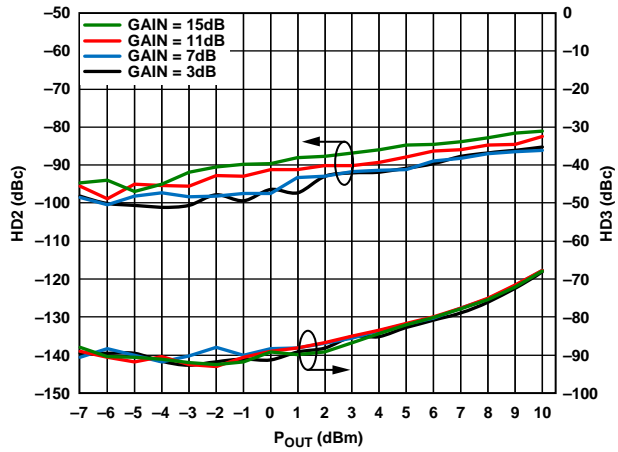


Figure 61. DGA HD2/HD3 vs. Output Power (P_{OUT}) and Gain Setting

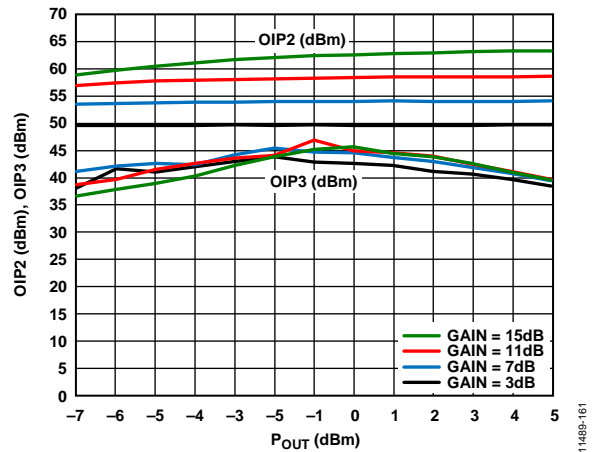


Figure 64. DGA OIP2/OIP3 vs. Output Power (P_{OUT}) and Gain Setting

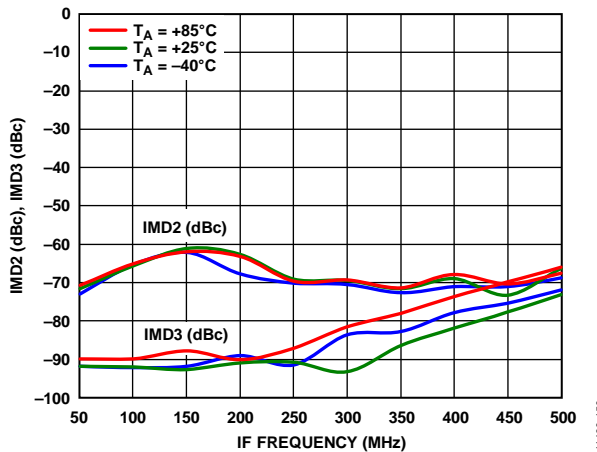


Figure 62. DGA IMD2/IMD3 vs. IF Frequency and Temperature; Maximum Gain

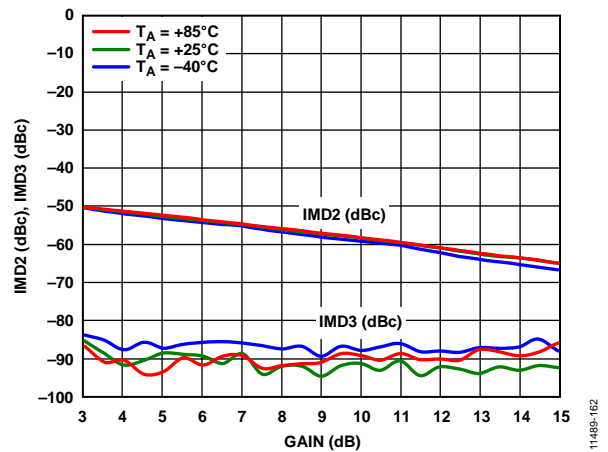


Figure 65. DGA IMD2/IMD3 vs. Gain Setting

SPURIOUS PERFORMANCE

($N \times f_{RF}$) – ($M \times f_{LO}$) spur measurements were made using the standard evaluation board. Mixer spurious products were measured in decibels (dB) relative to the carrier (dBc) from the IF output power level. Data is shown for all spurious components greater than –115 dBc and frequencies of less than 3 GHz.

915 MHz Performance

VCCX = 5 V, TA = 25°C, RF power = 0 dBm, internal LO, fRF = 914 MHz, fLO = 1114 MHz

| | | M | | | | | | |
|---|---|------|------|-------|-------|-------|-------|-------|
| | | 0 | 1 | 2 | 3 | 4 | 5 | 6 |
| N | 0 | | -34 | -35 | | | | |
| | 1 | -43 | 0 | -52 | -16 | | | |
| | 2 | -72 | -60 | -72 | -67 | -74 | | |
| | 3 | -102 | -73 | -103 | -78 | <-115 | -80 | |
| | 4 | | -102 | <-115 | <-115 | <-115 | <-115 | |
| | 5 | | | <-115 | -105 | <-115 | <-115 | <-115 |
| | 6 | | | | <-115 | <-115 | <-115 | <-115 |

1910 MHz Performance

VCCX = 5 V, TA = 25°C, RF power = 0 dBm, internal LO, fRF = 1910 MHz, fLO = 2110 MHz.

| | | M | | | | | | |
|---|---|---------|---------|----------|---------|----------|----------|-------|
| | | 0 | 1 | 2 | 3 | 4 | 5 | 6 |
| N | 0 | | -38.208 | | | | | |
| | 1 | -40.462 | -0.001 | -50.9 | | | | |
| | 2 | | -59.208 | -69.655 | -62.35 | | | |
| | 3 | | | -106.741 | -74.322 | -106.429 | | |
| | 4 | | | | <-115 | <-115 | <-115 | |
| | 5 | | | | <-115 | <-115 | -110.954 | |
| | 6 | | | | | | <-115 | <-115 |

2140 MHz Performance

VCCX = 5 V, TA = 25°C, RF power = 0 dBm, internal LO, fRF = 2140 MHz, fLO = 2340 MHz.

| | | M | | | | | | |
|---|---|-----|-----|-------|-------|-------|-------|-------|
| | | 0 | 1 | 2 | 3 | 4 | 5 | 6 |
| N | 0 | | -40 | | | | | |
| | 1 | -36 | 0 | -45 | | | | |
| | 2 | | -58 | -67 | -59 | | | |
| | 3 | | | <-115 | -74 | <-115 | | |
| | 4 | | | | <-115 | <-115 | <-115 | |
| | 5 | | | | | <-115 | <-115 | <-115 |
| | 6 | | | | | | <-115 | <-115 |

2700 MHz Performance

$V_{CCX} = 5\text{ V}$, $T_A = 25^\circ\text{C}$, RF power = 0 dBm, internal LO, $f_{RF} = 2700\text{ MHz}$, $f_{LO} = 2500\text{ MHz}$.

| | | M | | | | | | |
|---|---|---------|---------|--------|---------|-------|-------|-------|
| | | 0 | 1 | 2 | 3 | 4 | 5 | 6 |
| N | 0 | | -38.613 | | | | | |
| | 1 | -40.126 | -0.001 | -43.84 | | | | |
| | 2 | | -58.299 | -67.06 | -62.116 | | | |
| | 3 | | | | -73.603 | <-115 | | |
| | 4 | | | | | <-115 | <-115 | |
| | 5 | | | | | | <-115 | <-115 |
| | 6 | | | | | | | <-115 |

THEORY OF OPERATION

The **ADRF6620** integrates the essential elements of a multi-channel loopback receiver that is typically used in digital predistortion systems. The main features of the **ADRF6620** include a single-pole four throw (SP4T) RF input switch with tunable balun, variable attenuation, a wideband active mixer, and digitally programmable variable gain amplifier (DGA). In addition, the **ADRF6620** integrates a local oscillator (LO) generation block consisting of a synthesizer and a multicore voltage controlled oscillator (VCO) with an octave range and low phase noise. The synthesizer uses a fractional-N phase-locked loop (PLL) to enable continuous LO coverage from 350 MHz to 2850 MHz.

Putting all the building blocks of the **ADRF6620** together, the signal path through the device starts at the RF input, where one of four single-ended RF inputs is selected by the input mux and converted to a differential signal via a tunable balun. The differential RF signal is attenuated to an optimal input level via the digital step attenuator with 15 dB of attenuation range in steps of 1 dB. The RF signal is then mixed via a Gilbert cell mixer with the LO signal down to an IF frequency. The 255 Ω terminated differential output of the mixer is brought off chip to a pair of inductors and passed through an IF filter. The output of the IF filter is ac-coupled off chip and fed to an on-chip digital attenuator and IF DGA. The output of the IF DGA is then passed to an off-chip analog-to-digital converter (ADC).

RF INPUT SWITCHES

The **ADRF6620** integrates a SP4T switch where one of four RF inputs is selected. The desired RF input can be selected using either pin control or register writes via the SPI. Compared to the serial write approach, pin control allows faster control over the switch. When the RFSW0 pin (Pin 38) and the RFSW1 pin (Pin 39) are used, the RF switches can switch at speeds of up to

100 ns. When serial port control is used, the switch time is 100 ns, plus the latency of the SPI programming.

The RFSW_MUX bit (Register 0x23, Bit 11) selects whether the RF input switch is controlled via the external pins or the SPI port. By default at power-up, the device is configured for serial control. Writing to the RFSW_SEL bits (Register 0x23, Bits[10:9]) allows selection of one of the four RF inputs. Alternatively, by setting the RFSW_MUX bit high, the RFSW0 and RFSW1 pins can be used to select the RF input. Table 10 summarizes the different control options for the RF inputs.

To maintain good channel-to-channel isolation, ensure that unused RF inputs are properly terminated. The RFINx ports are internally terminated with 50 Ω resistors and have a dc bias level of 2.5 V. To avoid disrupting the dc level, the recommended termination is a dc blocking capacitor to GND. Figure 66 shows the recommended configuration when only RFIN0 is used, and the other RF input ports are properly terminated.

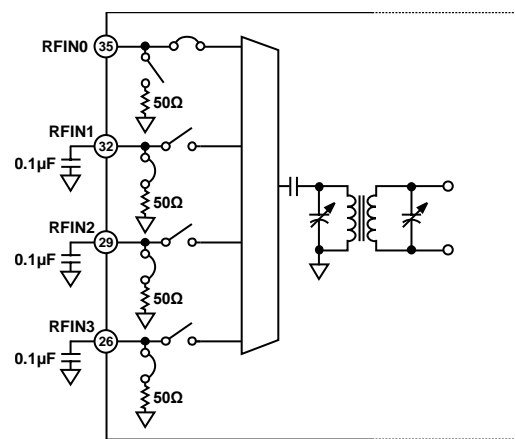


Figure 66. Terminating Unused RF Input Ports

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Table 10. RF Input Selection Table

| RFSW_MUX (Register Address 0x23[11]) | SPI Control, RFSW_SEL (Register Address 0x23[10:9]) | | Pin Control | | RF Input |
|--------------------------------------|---|----------------|----------------|----------------|----------|
| | Bit 10 | Bit 9 | RFSW1, Pin 39 | RFSW0, Pin 38 | |
| 0 | 0 | 0 | X ¹ | X ¹ | RFIN0 |
| 0 | 0 | 1 | X ¹ | X ¹ | RFIN1 |
| 0 | 1 | 0 | X ¹ | X ¹ | RFIN2 |
| 0 | 1 | 1 | X ¹ | X ¹ | RFIN3 |
| 1 | X ¹ | X ¹ | 0 | 0 | RFIN0 |
| 1 | X ¹ | X ¹ | 0 | 1 | RFIN1 |
| 1 | X ¹ | X ¹ | 1 | 0 | RFIN2 |
| 1 | X ¹ | X ¹ | 1 | 1 | RFIN3 |

¹X = don't care.

TUNABLE BALUN

The ADRF6620 integrates a programmable balun operating over a frequency range from 700 MHz to 2700 MHz. The tunable balun offers the benefit of ease of drivability from a single-ended 50 Ω RF input, and the single-ended-to-differential conversion of the balun optimizes common-mode rejection.

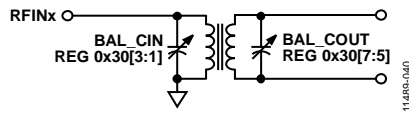


Figure 67. Integrated Tunable Balun

The RF balun is tuned by switching parallel capacitances on the primary and secondary sides by writing to Register 0x30. The added capacitance, in parallel with the inductive windings of the balun, changes the resonant frequency of the inductive capacitive (LC) tank. Therefore, selecting the proper combination of BAL_CIN (Register 0x30, Bits[3:1]) and BAL_COUT (Register 0x30, Bits[7:5]) sets the desired frequency and minimizes the insertion loss of the balun. Under most circumstances, the input and output can be tuned together; however, sometimes for matching reasons, it may be advantageous to tune them separately. See the RF Input Balun Insertion Loss Optimization section for the recommended BAL_CIN and BAL_COUT settings.

RF DIGITAL STEP ATTENUATOR (DSA)

The RF DSA follows the tunable balun. The attenuation range is 0 dB to 15 dB with a step size of 1 dB. DSA attenuation is set using the RFDSA_SEL bits (Register 0x23, Bits[8:5]).

ACTIVE MIXER

The double balanced mixer uses high performance SiGe NPN transistors. This mixer is based on the Gilbert cell design of four cross-connected transistors.

The mixer output has a 255 Ω differential output resistance. Bias the mixer outputs using either a pair of supply referenced RF chokes or an output transformer with the center tap connected to the positive supply.

DIGITALLY PROGRAMMABLE VARIABLE GAIN AMPLIFIER (DGA)

The ADRF6620 integrates a differential IF DGA consisting of a 150 Ω digitally controlled passive attenuator followed by a highly linear transconductance amplifier with feedback. The attenuation range is 12 dB, and the transconductor amplifier has a fixed gain of 15 dB. Therefore, at minimum attenuation, the gain of the IF DGA is 15 dB; at maximum attenuation, the gain is 3 dB. The attenuation is controlled by addressing the IF_ATTEN bits in Register 0x23, Bits[4:0]. The attenuation step size is 0.5 dB.

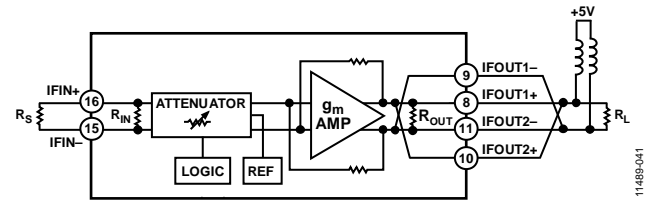


Figure 68. Simplified IF DGA Schematic

An independent internal voltage reference circuit sets the dc voltage level at the input of the amplifier to approximately 1.5 V. This reference is not accessible and cannot be adjusted.

The IF DGA consumes 35 mA through the VCC2 pin (Pin 12) and 75 mA through the two output choke inductors. The IF DGA can be powered down by disabling the IF_AMP_EN bit (Register 0x01, Bit 11). In its power-down state, the IF DGA current reduces to 6 mA. The dc bias level at the input remains at approximately 1.5 V when the DGA is disabled.

At minimum attenuation, the gain of the IF DGA is 15 dB when driving a 150 Ω load. The source and load resistance of the amplifier is set to 150 Ω in a matched condition. If the load or the source resistance is not equal to 150 Ω , the following equations can be used to determine the resulting gain and input/output resistances.

$$\text{Voltage Gain} = A_V = 0.044 \times (1000 || R_L)$$

$$R_{IN} = (1000 + R_L) / (1 + 0.044 \times R_L)$$

$$S21 (\text{Gain}) = 2 \times R_{IN} / (R_{IN} + R_S) \times A_V$$

$$R_{OUT} = (1000 + R_S) / (1 + 0.044 \times R_S)$$

The dc current to the outputs of each amplifier is supplied through two external choke inductors. The inductance of the chokes and the resistance of the load, in parallel with the output resistance of the device, add a low frequency pole to the response. The parasitic capacitance of the chokes adds to the output capacitance of the part. This total capacitance, in parallel with the load and output resistance, sets the high frequency pole of the device. In general, the larger the inductance of the choke, the higher the parasitic capacitance. Therefore, this trade-off must be considered when the value and type of the choke are selected.

For each polarity, the amplifier has two output pins that are oriented in an alternating fashion: IFOUT1+ (Pin 8), IFOUT1- (Pin 9), IFOUT2+ (Pin 10), and IFOUT2- (Pin 11). When designing the board, minimize the parasitic capacitance caused by routing the corresponding outputs together. See the Layout section for the recommended printed circuit board (PCB) layout.

LO GENERATION BLOCK

The ADRF6620 offers two modes for sourcing the LO signal to the mixer. The first mode uses the on-chip PLL and VCO. This mode of operation provides a high quality LO that meets the performance requirements of most applications. Using the on-chip synthesizer and VCO removes the burden of generating and distributing a high frequency LO signal.

The second mode bypasses the integrated LO generation block and allows the LO to be supplied externally. This second mode can provide a very high quality signal directly to the mixer core. Sourcing the LO signal externally may be necessary in demanding applications that require the lowest possible phase noise performance.

External LO Mode

External or internal LO mode can be selected via the VCO_SEL bits (Register 0x22, Bits[2:0]). To configure for external LO mode, set Register 0x22, Bits[2:0] to 011 and apply the differential LO signals to Pin 44 (LOIN-) and Pin 45 (LOIN+). The external LO frequency range is 350 MHz to 3.2 GHz. The ADRF6620 offers the flexibility of using a higher LO frequency signal and dividing it down before it drives the mixer. The LO divider can be found in the LO_DIV_A bits (Register 0x22, Bits[4:3]), where options include ÷1, ÷2, ÷4, or ÷8.

The external LO input pins present a broadband differential 50 Ω input impedance. The LOIN+ and LOIN- input pins must be ac-coupled. When not in use, LOIN+ and LOIN- can be left unconnected.

Internal LO Mode

The ADRF6620 includes an on-chip VCO and PLL for LO synthesis. The PLL, shown in Figure 69, consists of a reference input, phase and frequency detector (PFD), charge pump, and a programmable integer divider with prescaler. The reference path takes in a reference clock and divides it down by a factor of 1, 2, 4, or 8 or multiplies it by a factor of 2 before passing it to the PFD. The PFD compares this signal to the divided down signal from the VCO. Depending on the PFD polarity selected, the PFD sends an up/down signal to the charge pump if the VCO signal is slow/fast compared to the reference frequency. The charge pump sends a current pulse to the off-chip loop filter to increase or decrease the tuning voltage (VTUNE).

The ADRF6620 integrates three VCO cores that cover an octave range from 2.8 GHz to 5.7 GHz. Table 11 summarizes the frequency range for each VCO. The desired VCO can be selected by addressing the VCO_SEL bits (Register 0x22, Bits[2:0]).

Table 11. VCO Range

| VCO_SEL (Register 0x22, Bits[2:0]) | Frequency Range (GHz) |
|------------------------------------|-----------------------|
| 000 | 5.2 to 5.7 |
| 001 | 4.1 to 5.2 |
| 010 | 2.8 to 4.1 |
| 011 | External LO |

The N-divider divides down the differential VCO signal to the PFD frequency. The N-divider can be configured for fractional mode or integer mode by addressing the DIV_MODE bit (Register 0x02, Bit 11). The default configuration is set for fractional mode.

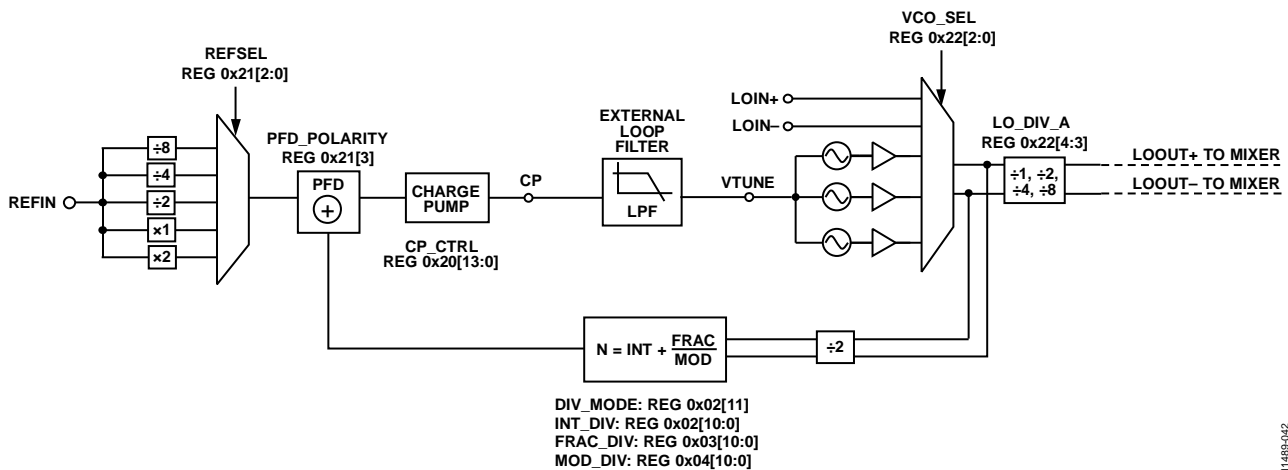


Figure 69. LO Generation Block Diagram

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The following equations can be used to determine the N value and PLL frequency:

$$f_{\text{PFD}} = \frac{f_{\text{VCO}}}{2 \times N}$$

$$N = \text{INT} + \frac{\text{FRAC}}{\text{MOD}}$$

$$f_{\text{LO}} = \frac{f_{\text{PFD}} \times 2 \times N}{\text{LO_DIVIDER}}$$

where:

f_{PFD} is the phase frequency detector frequency.

f_{VCO} is the voltage controlled oscillator frequency.

N is the fractional divide ratio (INT + FRAC/MOD)

INT is the integer divide ratio programmed in Register 0x02.

FRAC is the fractional divider programmed in Register 0x03.

MOD is the modulus divide ratio programmed in Register 0x04.

f_{LO} is the LO frequency going to the mixer core when the loop is locked.

LO_DIVIDER is the final divider block that divides the VCO frequency down by 1, 2, 4, or 8 before it reaches the mixer (see Table 12). This control is located in the LO_DIV_A bits (Register 0x22, Bits[4:3]).

Table 12. LO Divider

| LO_DIV_A (Register 0x22, Bits[4:3]) | LO_DIVIDER |
|-------------------------------------|------------|
| 00 | 1 |
| 01 | 2 |
| 10 | 4 |
| 11 | 8 |

The lock detect signal is available as one of the selectable outputs through the MUXOUT pin; a logic high indicates that the loop is locked. The MUXOUT pin is controlled by the REF_MUX_SEL bits (Register 0x21, Bits[6:4]); the PLL lock detect signal is the default configuration.

To ensure that the PLL locks to the desired frequency, follow the proper write sequence of the PLL registers. The PLL registers must be configured accordingly to achieve the desired frequency, and the last writes must be to Register 0x02 (INT_DIV), Register 0x03 (FRAC_DIV), or Register 0x04 (MOD_DIV). When one of these registers is programmed, an internal VCO calibration is initiated, which is the last step in locking the PLL.

The time it takes to lock the PLL after the last register is written can be broken down into two parts: VCO band calibration and loop settling.

After the last register is written, the PLL automatically performs a VCO band calibration to choose the correct VCO band. This calibration takes approximately 5120 PFD cycles. For a 40 MHz f_{PFD} , this corresponds to 128 μs . After calibration is complete, the feedback action of the PLL causes the VCO to eventually lock to the correct frequency. The speed with which this locking occurs depends on the nonlinear cycle-slipping behavior, as well as the small-signal settling of the loop. For an accurate estimation of the lock time, download the [ADIsimPLL](#) tool, which correctly

captures these effects. In general, higher bandwidth loops tend to lock more quickly than lower bandwidth loops.

Additional LO Controls

To access the LO signal going to the mixer core through the LOOUT+ and LOOUT– pins (Pin 21 and Pin 22), enable the LO_DRV_EN bit in Register 0x01, Bit 7. This setting offers direct monitoring of the LO signal to the mixer for debug purposes; or the LO signal can be used to daisy-chain many devices synchronously. One [ADRF6620](#) can serve as the master where the LO signal is sourced, and the subsequent slave devices share the same LO signal from the master. This flexibility substantially eases the LO requirements of a system with multiple LOs.

The LO output drive level is controlled by the LO_DRV_LVL bits (Register 0x22, Bits[8:7]). Table 13 shows the available drive levels.

Table 13. LO Drive Level

| LO_DRV_LVL (Register 0x22, Bits[8:7]) | Amplitude (dBm) |
|---------------------------------------|-----------------|
| 00 | –4 |
| 01 | 0.5 |
| 10 | 3 |
| 11 | 4.5 |

SERIAL PORT INTERFACE (SPI)

The SPI port of the [ADRF6620](#) allows the user to configure the device through a structured register space provided inside the chip. Registers are accessed via the serial port interface and can be written to or read from via the serial port interface.

The serial port interface consists of three control lines: SCLK, SDIO, and CS. SCLK (serial clock) is the serial shift clock. The SCLK signal clocks data on its rising edge. SDIO (serial data input/output) is an input or output depending on the instruction being sent and the relative position in the timing frame. CS (chip select bar) is an active low control that gates the read and write cycles. The falling edge of CS, in conjunction with the rising edge of SCLK, determines the start of the frame. All SCLK and SDIO activity is ignored when CS is high. Table 6 and Figure 2 show the serial timing and its definitions.

The [ADRF6620](#) protocol consists of seven register address bits, followed by a read/write indicator and 16 data bits. Both the address and data fields are organized from MSB to LSB.

On a write cycle, up to 16 bits of serial write data are shifted in, MSB to LSB. If the rising edge of CS occurs before the LSB of the serial data is latched, only the bits that were clocked in are written to the device. If more than 16 data bits are shifted in, the 16 most recent bits are written to the device. The [ADRF6620](#) input logic level for the write cycle supports a logic level as low as 1.8 V.

On a read cycle, up to 16 bits of serial read data are shifted out, MSB to LSB. Data shifted out beyond 16 bits is undefined. It is not necessary for readback content at a given register address to correspond with the write data of the same address. The output logic level for a read cycle is 2.5 V.

BASIC CONNECTIONS

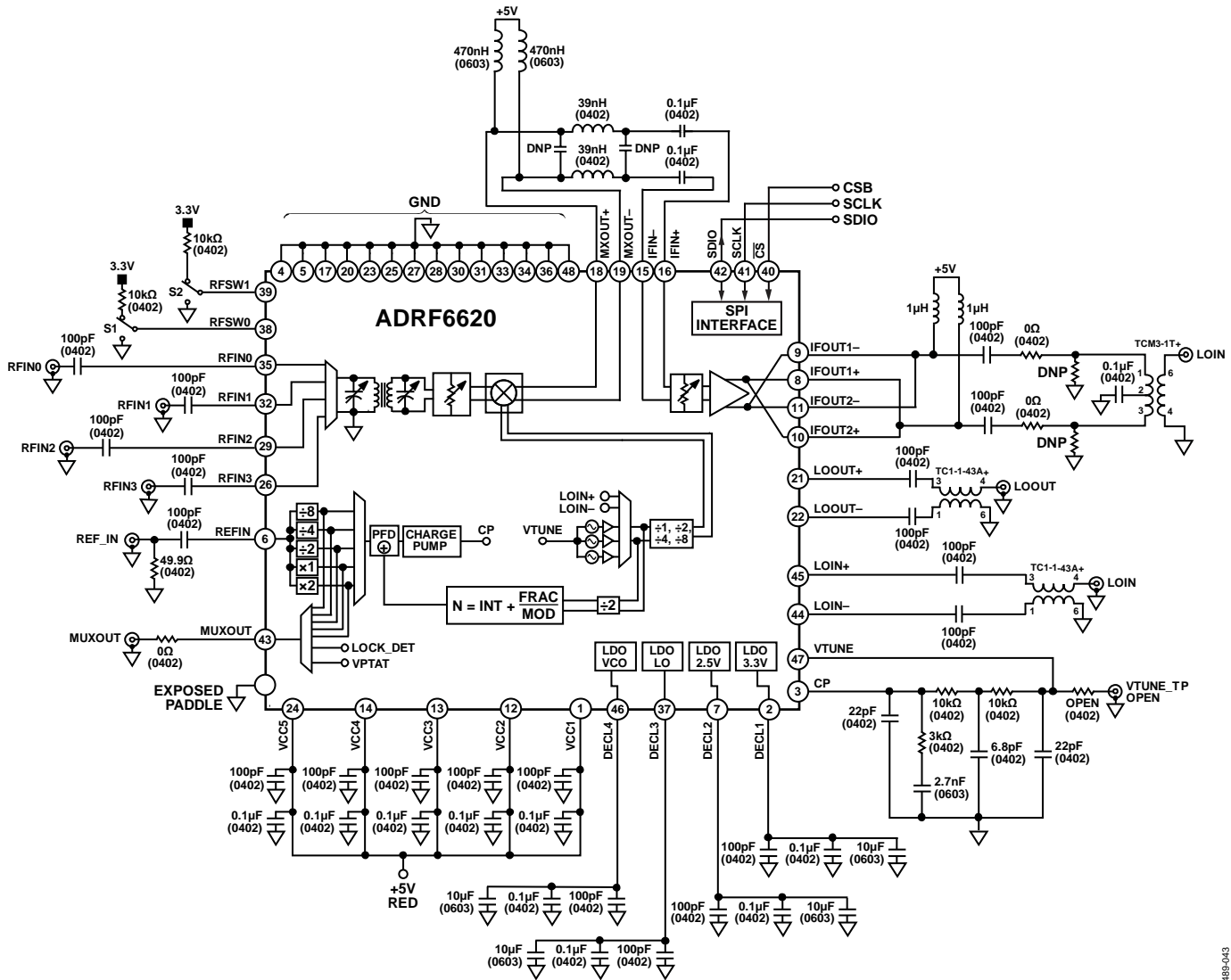


Figure 70. Basic Connection Diagram

Table 14. Basic Connections

| Pin No. | Mnemonic | Description | Basic Connection |
|----------|----------------|---------------------------------------|--|
| 5V Power | | | |
| 1 | VCC1 | LO, VCO, mixer power supply | Decouple all power supply pins to ground using 100 pF and 0.1 μF capacitors. Place the decoupling capacitors close to the pins. |
| 12 | VCC2 | IF DGA power supply | |
| 13 | VCC3 | Factory calibration pin | |
| 14 | VCC4 | Factory calibration pin | |
| 24 | VCC5 | RF front-end power supply | |
| PLL/VCO | | | |
| 3 | CP | Synthesizer charge pump output | Connect this pin to the VTUNE pin through the loop filter. |
| 6 | REFIN | Synthesizer reference frequency input | The nominal input level of this pin is 1 V p-p. The input range is 12 MHz to 464 MHz. This pin is internally biased and must be ac-coupled and terminated externally with a 50 Ω resistor. Place the ac coupling capacitor between the pin and the resistor. When driven from an 50 Ω RF signal generator, the recommended input level is 4 dBm. |
| 21, 22 | LOOUT+, LOOUT- | Differential LO outputs | The differential output impedance of these pins is 50 Ω. The pins |

| Pin No. | Mnemonic | Description | Basic Connection |
|---|---------------------------------------|------------------------------|--|
| 44, 45 | LOIN-, LOIN+ | Differential LO inputs | are internally biased to 2.5 V and must be ac-coupled. |
| 43 | MUXOUT | PLL multiplex output | The differential input impedance of these pins is 50 Ω . The pins are internally biased to 2.5 V and must be ac-coupled. |
| 47 | VTUNE | VCO tuning voltage | This output pin provides the PLL reference signal or the PLL lock detect signal. |
| RF Inputs 26, 29, 32, 35 | RFIN3, RFIN2 RFIN1, RFIN0 | RF inputs | This pin is driven by the output of the loop filter; its nominal input voltage range is 1.5 V to 2.5 V. |
| 38, 39 | RFSW0, RFSW1 | Pin control of the RF inputs | The single-ended RF inputs have a 50 Ω input impedance and are internally biased to 2.5 V. These pins must be ac-coupled. Terminate unused RF inputs with a dc blocking capacitor to GND to improve isolation. Refer to the Layout section for the recommended PCB layout for optimized channel-to-channel isolation. |
| IF DGA 8, 9, 10, 11 | IFOUT1+, IFOUT1-, IFOUT2+, IFOUT2- | IF DGA outputs | See Table 10 for the pin settings for RF input pin control. For logic high, connect these pins to 2.5 V logic. |
| 15, 16 | IFIN-, IFIN+ | IF DGA inputs | The differential IF DGA outputs have two output pins for each polarity. They are oriented in alternating fashion: IFOUT1+ (Pin 8), IFOUT1- (Pin 9), IFOUT2+ (Pin 10), and IFOUT2- (Pin 11). Connect the positive pins such that IFOUT1+ and IFOUT2+ are tied together. Similarly, connect the negative pins such that IFOUT1- and IFOUT2- are tied together. Refer to the Layout section for a recommended layout that minimizes parasitic capacitance and optimizes on performance. |
| Mixer Outputs 18, 19 | MXOUT+, MXOUT- | Differential mixer outputs | The output stage of the IF DAG is an open-collector configuration that requires a dc bias of 5 V. Use bias choke inductors to achieve this configuration. Choose the bias choke inductors such that they can handle a maximum current of 50 mA on each side. By design, the IF DGA is optimized for linearity when the source and load are terminated with 150 Ω . |
| Serial Port Interface 40 | \overline{CS} | SPI chip select | AC couple the mixer outputs to the IF DGA inputs. See the Interstage Filtering Requirements section for the recommended filter designs. |
| 41 | SCLK | SPI clock | Active low. 3.3 V logic levels. |
| 42 | SDIO | SPI data input and output | 3.3 V tolerant logic levels. |
| LDO Decoupling 2 | DECL1 | 3.3 V LDO decoupling | 3.3 V tolerant logic levels. |
| 7 | DECL2 | 2.5 V LDO decoupling | |
| 37 | DECL3 | LO LDO decoupling | Decouple all DECLx pins to ground using 100 pF, 0.1 μ F, and 10 μ F capacitors. Place the decoupling capacitors close to the pin. |
| 46 | DECL4 | VCO LDO decoupling | |
| GND 4, 5, 17, 20, 23, 25, 27, 28, 30, 31, 33, 34, 36, 48 | GND | Ground | Connect these pins to the GND of the PCB. |
| 49 (EPAD) | | Exposed pad (EPAD) | The exposed thermal pad is on the bottom of the package. The exposed pad must be soldered to ground. |

RF INPUT BALUN INSERTION LOSS OPTIMIZATION

As shown in Figure 71 to Figure 74, the gain of the [ADRF6620](#) mixer has been characterized for every combination of BAL_CIN and BAL_COUT (Register 0x30). As shown, a range of BAL_CIN and BAL_COUT values can be used to optimize the gain of the [ADRF6620](#). The optimized values do not change with temperature. After the values are chosen, the absolute gain changes over temperature; however, the signature of the BAL_CIN and BAL_COUT values is fixed.

At lower input frequencies, more capacitance is needed. This increase is achieved by programming higher codes into BAL_CIN and BAL_COUT. At high frequencies, less capacitance is required; therefore, lower BAL_CIN and BAL_COUT codes are appropriate. Table 16 provides a list of recommended BAL_CIN and BAL_COUT codes for popular radio frequencies. Use Figure 71 to Figure 74 and Table 16 only as guides; do not interpret them in the absolute sense because every application and PCB design varies. Additional fine-tuning may be necessary to achieve the maximum gain.

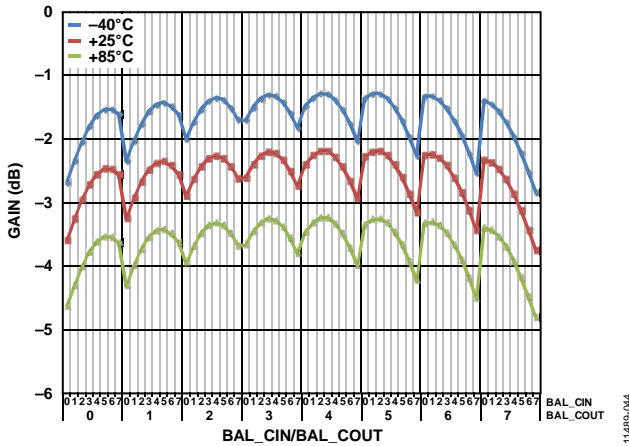


Figure 71. Gain vs. BAL_CIN and BAL_COUT at RF = 900 MHz

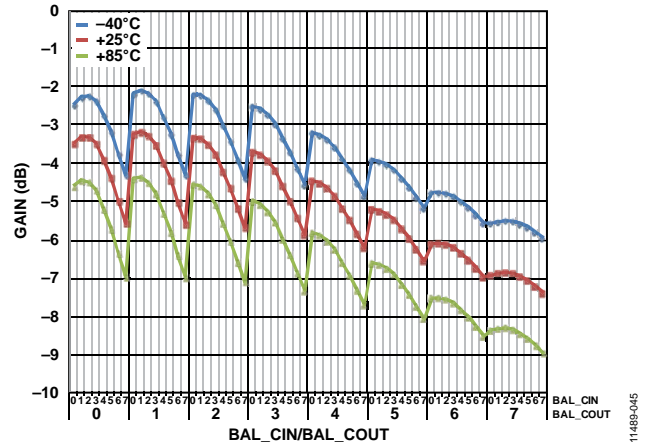


Figure 73. Gain vs. BAL_CIN and BAL_COUT at RF = 1900 MHz

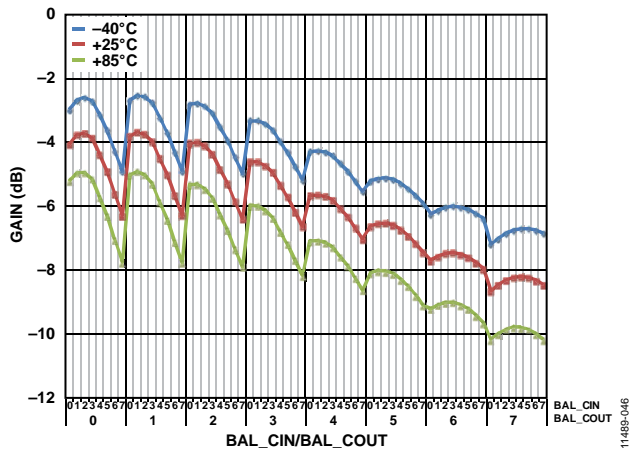


Figure 72. Gain vs. BAL_CIN and BAL_COUT at RF = 2100 MHz

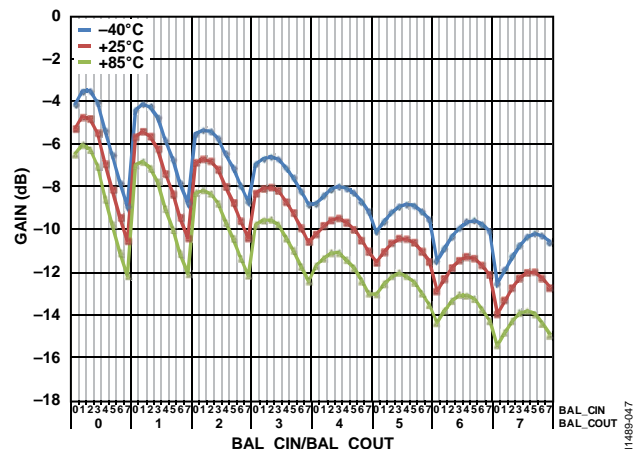


Figure 74. Gain vs. BAL_CIN and BAL_COUT at RF = 2700 MHz

IP3 AND NOISE FIGURE OPTIMIZATION

The [ADRF6620](#) can be configured for either improved performance or reduced power consumption. In applications where performance is critical, the [ADRF6620](#) offers IP3 or noise figure optimization. However, if power consumption is the priority, the mixer bias current can be reduced to save on the overall power at the expense of degraded performance. Whatever the application specific needs are, the [ADRF6620](#) offers configurability that balances performance and power consumption.

Adjustments to the mixer bias setting have the most impact on performance and power. For this reason, mixer bias should be the first adjustment. The active mixer core of the [ADRF6620](#) is a linearized transconductor. With increased bias current, the transconductor becomes more linear, resulting in higher IP3. The improved IP3, however, is at the expense of degraded noise figure and increased power consumption (see Figure 75). For a 1-bit change of the mixer bias (MIXER_BIAS, Register 0x31, Bits[11:9]), the current increases by 7.71 mA.

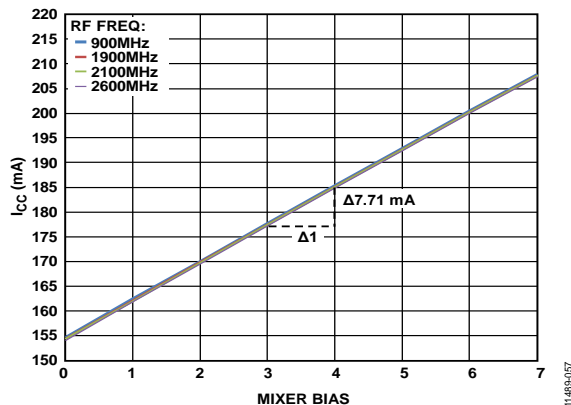


Figure 75. Change in Current Consumption vs. MIXER_BIAS

Inevitably, there is a limit on how much the bias current can increase before the improvement in linearity no longer justifies the increase in power and noise. The mixer core reaches a saturation point where further increases in bias current do not translate to improved performance. When that point is reached, it is best to decrease the bias current to a level where the desired performance is achieved. Depending on the system specifications of the customer, a balance between linearity, noise figure, and power can be attained.

In addition to bias optimization, the [ADRF6620](#) also has configurable distortion cancellation circuitry. The linearized transconductor input of the [ADRF6620](#) is made up of a main path and a secondary path. Through adjustments of the amplitude and phase of the secondary path, the distortion generated by the main path can be canceled, resulting in improved IPd3 performance. The amplitude and phase adjustments are located in the following serial interface bits: MIXER_RDAC (Register 0x31, Bits[8:5]) and MIXER_CDAC (Register 0x31, Bits[4:0]).

Figure 76 to Figure 83 show the IIP3 and noise figure sweeps for all MIXER_RDAC, MIXER_CDAC, and MIXER_BIAS combinations. The IIP3 vs. MIXER_RDAC and MIXER_CDAC figures show both a surface and a contour plot in one figure. The contour plot is located directly underneath the surface plot. The best approach for reading the figure is to localize the peaks on the surface plot, which indicate maximum IIP3, and to follow the same color pattern to the contour plot to determine the optimized MIXER_RDAC and MIXER_CDAC values. The overall shape of the IIP3 plot does not vary with the MIXER_BIAS setting; therefore, only MIXER_BIAS = 011 is displayed.

The data shows that MIXER_BIAS has the largest impact on performance. As previously mentioned and evident in the data, IIP3 improves with increased MIXER_BIAS, and noise figure is optimized at the lowest bias setting. Taking a more detailed look at the data, the different MIXER_RDAC and MIXER_CDAC combinations can result in a ~5 dB to +10 dB change in IIP3, but the noise figure changes by only ~0.5 dB. These trends become very important in deciding the trade-offs between IP3, noise figure, and power consumption. The total current consumption of the ADRF6620 does not change with MIXER_RDAC and MIXER_CDAC and varies only with the mixer bias settings (see Figure 75).

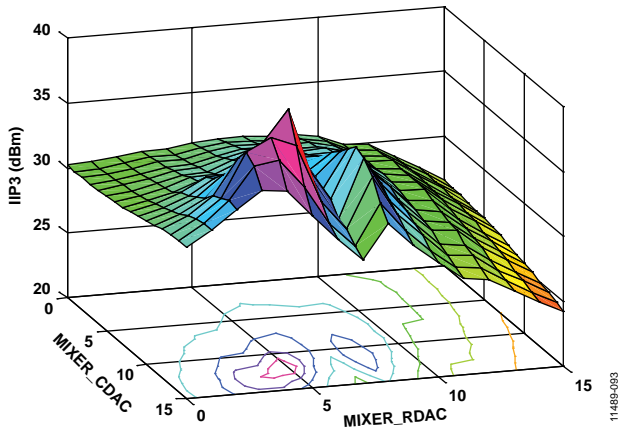


Figure 76. IIP3 vs. MIXER_RDAC, MIXER_CDAC; MIXER_BIAS = 011 at RF Frequency = 900 MHz

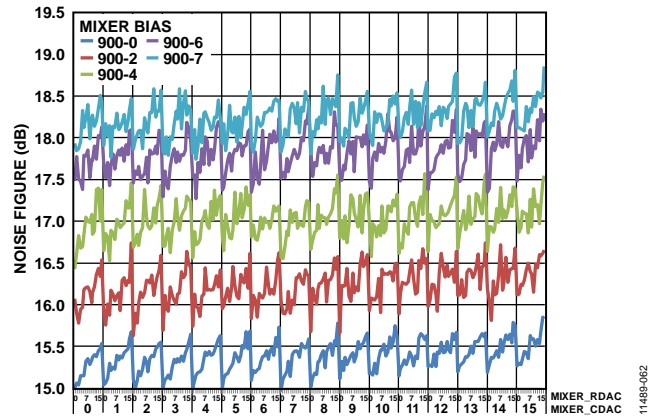


Figure 78. Noise Figure vs. MIXER_RDAC, MIXER_CDAC, and Various MIXER_BIAS Values at RF Frequency = 900 MHz

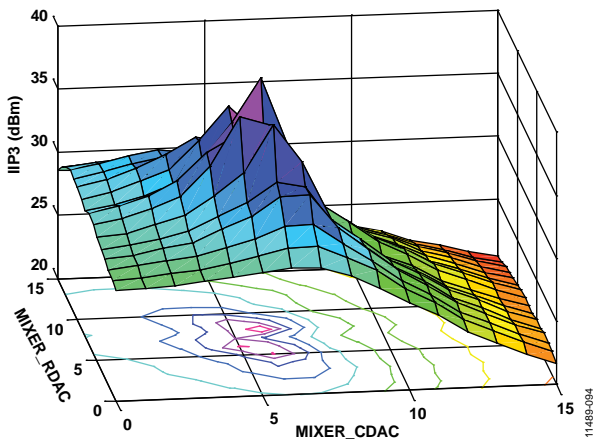


Figure 77. IIP3 vs. MIXER_RDAC, MIXER_CDAC; MIXER_BIAS = 011 at RF Frequency = 1900 MHz

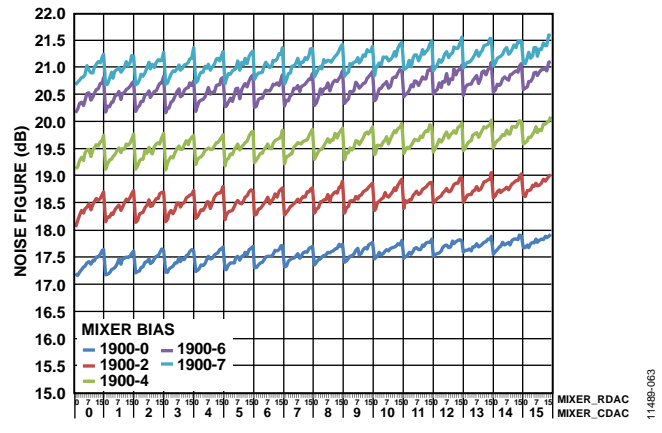


Figure 79. Noise Figure vs. MIXER_RDAC, MIXER_CDAC, and Various MIXER_BIAS Values at RF Frequency = 1900 MHz

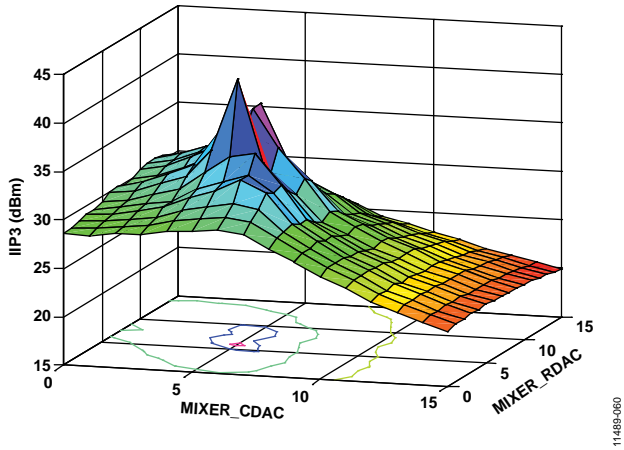


Figure 80. IIP3 vs. MIXER_RDAC, MIXER_CDAC; MIXER_BIAS = 011 at RF Frequency = 2100 MHz

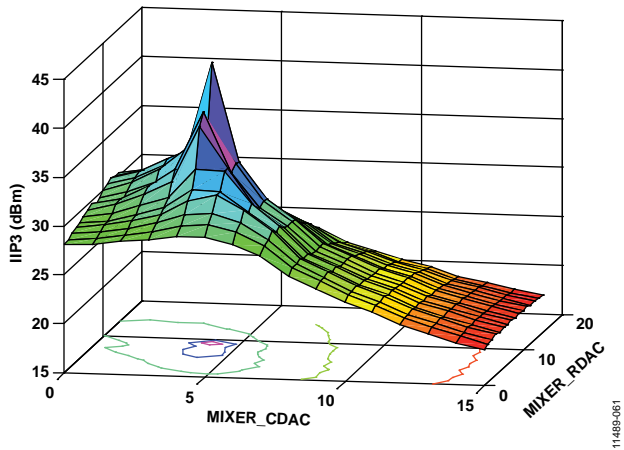


Figure 81. IIP3 vs. MIXER_RDAC, MIXER_CDAC; MIXER_BIAS = 011 at RF Frequency = 2700 MHz

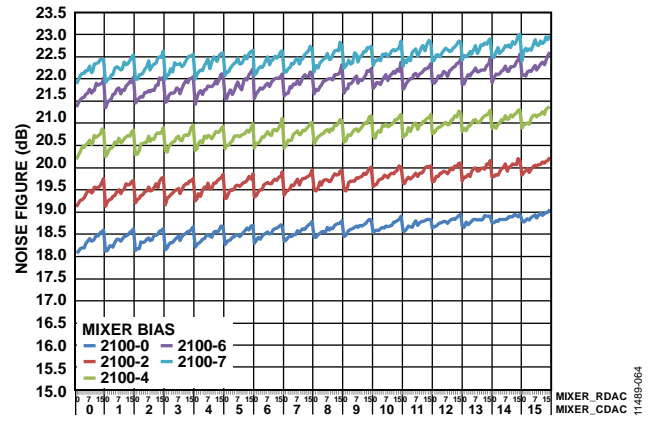


Figure 82. Noise Figure vs. MIXER_RDAC, MIXER_CDAC, and Various MIXER_BIAS Values at RF Frequency = 2100 MHz

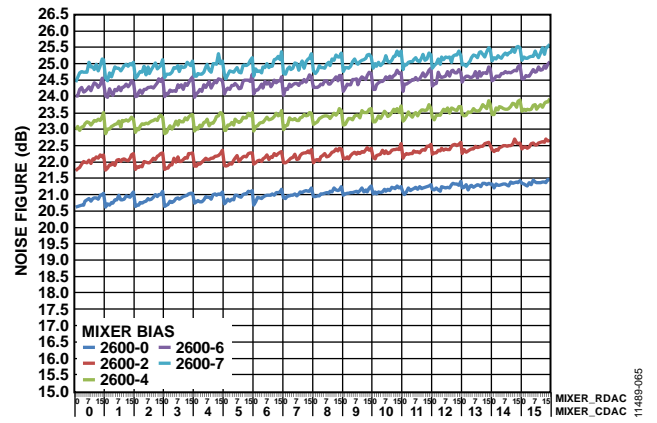


Figure 83. Noise Figure vs. MIXER_RDAC, MIXER_CDAC, and Various MIXER_BIAS Values at RF Frequency = 2700 MHz

As an example, the MIXER_RDAC, MIXER_CDAC, and MIXER_BIAS settings of the ADRF6620 were carefully selected, based on three individual goals that resulted in three sets of MIXER_RDAC, MIXER_CDAC, and MIXER_BIAS values. The first goal was for optimized IIP3. To achieve the most optimal IIP3 performance, the MIXER_BIAS was set to a higher current setting, and MIXER_RDAC and MIXER_CDAC were selected at the peaks. This configuration allowed for the most optimal IIP3 performance. However, it also consumed the most power, and the noise figure was degraded. The second goal was to achieve a balance among IIP3, the noise figure, and power consumption. Finally, the third goal was for an optimized noise figure. This configuration resulted in the lowest power consumption while IIP3 was not optimized. Table 15 summarizes the test conditions; Table 16 shows the corresponding MIXER_RDAC, MIXER_CDAC, and MIXER_BIAS values. The resulting IIP3 and noise figure performance for the

specific MIXER_RDAC, MIXER_CDAC, and MIXER_BIAS settings are shown in Figure 84.

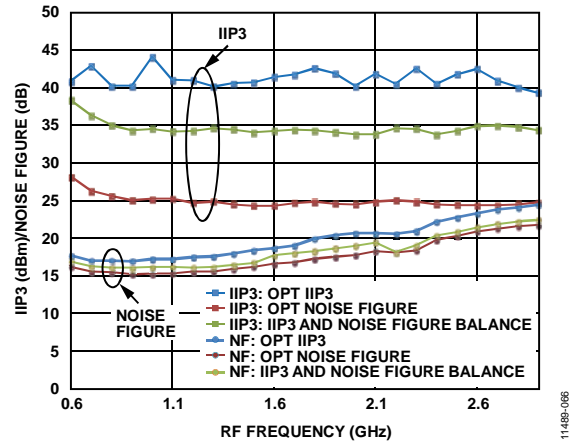


Figure 84. Example IIP3 and Noise Figure Optimization

Table 15. Mixer Optimization Summary

| Parameter | Test Conditions/Comments |
|---|--|
| Optimized IIP3 | MIXER_RDAC, MIXER_CDAC, and MIXER_BIAS were configured for optimized IIP3 performance. |
| Noise Figure, IIP3, and Power Consumption Balance | MIXER_BIAS was limited to 0, 1, or 2 decimal for improved noise figure while allowing IIP3 to degrade. MIXER_RDAC and MIXER_CDAC were chosen for optimized IIP3 because MIXER_RDAC and MIXER_CDAC have a larger impact on IIP3 than on noise figure. |
| Optimized Noise Figure | MIXER_BIAS was set to 0 decimal for the best noise figure. MIXER_RDAC and MIXER_CDAC were chosen for optimized IIP3 because they have a larger impact on IIP3 than on noise figure. |

Table 16. Recommended BAL_CIN, BAL_COUT, MIXER_RDAC, MIXER_CDAC, and MIXER_BIAS Settings (in Decimal)

| RF Frequency (MHz) | BAL_CIN | BAL_COUT | Optimized IIP3 | | | IIP3 and Noise Figure Balance | | | Optimized Noise Figure | | |
|--------------------|---------|----------|----------------|------|------|-------------------------------|------|------|------------------------|------|------|
| | | | RDAC | CDAC | BIAS | RDAC | CDAC | BIAS | RDAC | CDAC | BIAS |
| 600 | 7 | 7 | 6 | 10 | 4 | 4 | 15 | 2 | 4 | 15 | 0 |
| 700 | 7 | 7 | 5 | 14 | 4 | 4 | 15 | 2 | 4 | 15 | 0 |
| 800 | 5 | 5 | 3 | 13 | 3 | 3 | 14 | 2 | 2 | 15 | 0 |
| 900 | 3 | 4 | 0 | 15 | 0 | 3 | 13 | 2 | 2 | 14 | 0 |
| 940 | 3 | 3 | 5 | 12 | 4 | 5 | 11 | 2 | 2 | 13 | 0 |
| 1000 | 2 | 3 | 5 | 11 | 4 | 4 | 10 | 2 | 3 | 11 | 0 |
| 1100 | 1 | 2 | 5 | 10 | 4 | 3 | 10 | 1 | 2 | 11 | 0 |
| 1200 | 1 | 2 | 5 | 9 | 4 | 3 | 9 | 1 | 2 | 10 | 0 |
| 1300 | 0 | 2 | 8 | 8 | 4 | 3 | 9 | 1 | 2 | 10 | 0 |
| 1400 | 0 | 2 | 6 | 7 | 4 | 4 | 8 | 1 | 2 | 9 | 0 |
| 1500 | 0 | 2 | 6 | 7 | 4 | 5 | 7 | 2 | 3 | 8 | 0 |
| 1600 | 0 | 2 | 8 | 7 | 4 | 5 | 7 | 2 | 2 | 8 | 0 |
| 1700 | 0 | 1 | 6 | 6 | 4 | 5 | 6 | 2 | 4 | 7 | 0 |
| 1800 | 0 | 1 | 9 | 6 | 4 | 5 | 6 | 2 | 4 | 7 | 0 |
| 1840 | 0 | 1 | 9 | 6 | 5 | 5 | 6 | 2 | 3 | 7 | 0 |
| 1900 | 0 | 1 | 9 | 6 | 5 | 6 | 5 | 2 | 3 | 7 | 0 |
| 2000 | 0 | 1 | 7 | 5 | 5 | 3 | 6 | 0 | 3 | 6 | 0 |
| 2100 | 1 | 1 | 9 | 5 | 5 | 5 | 5 | 1 | 3 | 6 | 0 |
| 2140 | 1 | 1 | 9 | 5 | 4 | 5 | 5 | 1 | 3 | 6 | 0 |
| 2200 | 2 | 0 | 7 | 4 | 4 | 5 | 5 | 1 | 3 | 6 | 0 |
| 2300 | 2 | 0 | 7 | 4 | 4 | 5 | 5 | 1 | 3 | 6 | 0 |
| 2400 | 1 | 0 | 7 | 4 | 4 | 5 | 5 | 1 | 3 | 6 | 0 |
| 2500 | 1 | 0 | 7 | 4 | 4 | 5 | 5 | 1 | 3 | 6 | 0 |
| 2600 | 1 | 0 | 7 | 4 | 4 | 5 | 5 | 1 | 3 | 6 | 0 |
| 2700 | 1 | 0 | 7 | 4 | 4 | 5 | 5 | 1 | 3 | 6 | 0 |
| 2800 | 1 | 0 | 7 | 4 | 4 | 4 | 15 | 2 | 4 | 15 | 0 |
| 2900 | 1 | 0 | 7 | 4 | 4 | 4 | 15 | 2 | 4 | 15 | 0 |
| 3000 | 0 | 0 | 7 | 4 | 4 | 3 | 14 | 2 | 2 | 15 | 0 |

INTERSTAGE FILTERING REQUIREMENTS

Filtering at the mixer output may be necessary for improved linearity performance. For applications where the frequency plan requires low RF frequency inputs and IF outputs, the resulting sum term at the mixer outputs, $f_{RF} + f_{LO}$, may fall within the band of interest. The unwanted sum term may cause the IF DGA to operate in its nonlinear region because of the unnecessary presence of additional signal power. As a result, the linearity performance degrades where OIP3 and OIP2 decrease substantially. For this reason, a low-pass filter is necessary to attenuate the unwanted signal while maintaining the integrity of the wanted signal within the band of interest. In addition, the low-pass filter serves to suppress the LO feedthrough. Because of the absence of blockers in a typical DPD receive application, a lower order filter, such as a third-order Chebyshev, is typically adequate.

The low-pass filter resides between the mixer outputs and the IF DGA inputs, as shown in Figure 85. The signal flow starts with the differential outputs of the mixer being dc biased to positive supply (5 V) via a pair of pull-up inductors, L1 and L2. The inductor value is determined by the low frequency cutoff of the signal band of interest. Next, the third-order low-pass filter attenuates the high frequency sum term. The combination of the pull-up inductors and the low-pass filter results in a band-pass filter profile. The outputs of the filter are then ac-coupled through series capacitors and routed to the on-chip IF DGA via the IFIN+ and IFIN- pins.

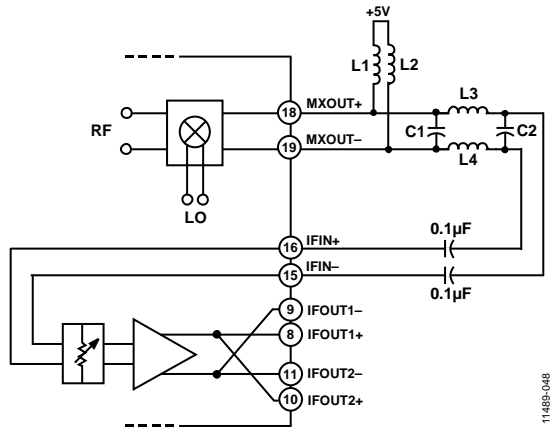


Figure 85. Low-Pass IF Filter

When designing the low-pass filter, it is important to consider the output impedance of the mixer and the input impedance of the IF DGA. The output impedance of the mixer has both a real and reactive component, and its equivalent model is shown in Figure 86. Correspondingly, Figure 87 shows the impedance vs. frequency for the mixer output.

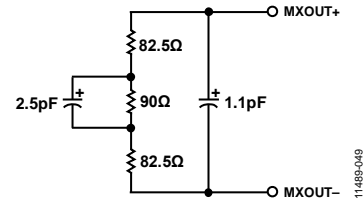


Figure 86. Equivalent Model of the Mixer Output Impedance

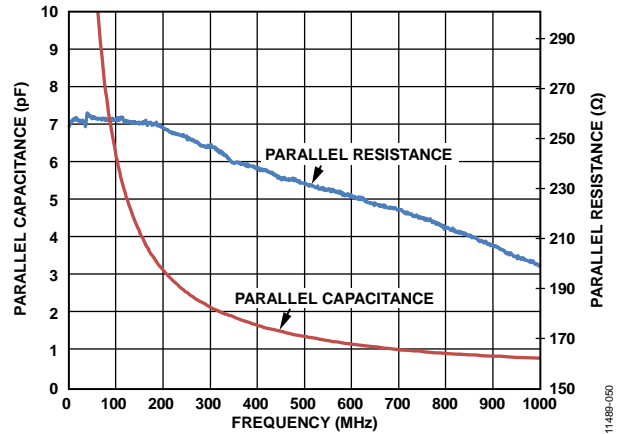


Figure 87. Mixer Output Impedance vs. Frequency

Likewise, Figure 88 shows the impedance vs. frequency for the IF DGA. The four-port S parameter files for the IF DGA and mixer are available on analog.com and can serve as a useful tool to accurately capture the input and output impedance when designing the interstage filter. As a first-order approximation at low frequencies, the mixer output has a fixed impedance of approximately 255 Ω, and the input impedance of the IF DAG is approximately 150 Ω. Therefore, design the low-pass filter to have an input impedance of 255 Ω and an output impedance of 150 Ω.

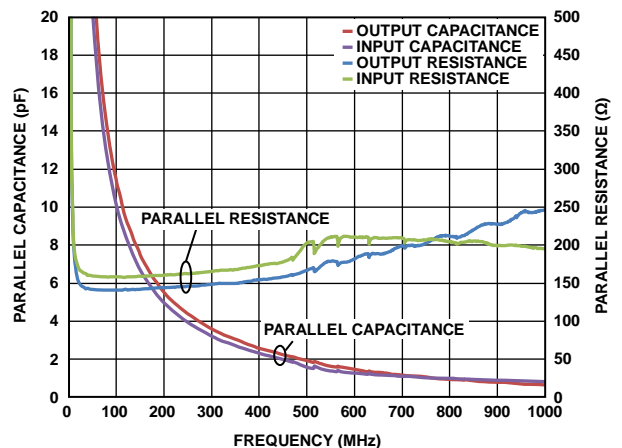


Figure 88. IF DGA Input/Output Impedance vs. Frequency

Most important, the low-pass interstage filter must attenuate the sum term ($f_{RF} + f_{LO}$) and LO feedthrough to prevent unnecessary overdrive of the DGA. The level of attenuation that is required to achieve optimal OIP3 performance is shown in Figure 89, where OIP3 vs. ($f_{RF} + f_{LO}$) amplitude is plotted. To maintain performance, attenuate the amplitude of the sum term to at least -16 dBm (see Figure 89). Beyond this point, the OIP3 degrades decibel per decibel for increased amplitudes.

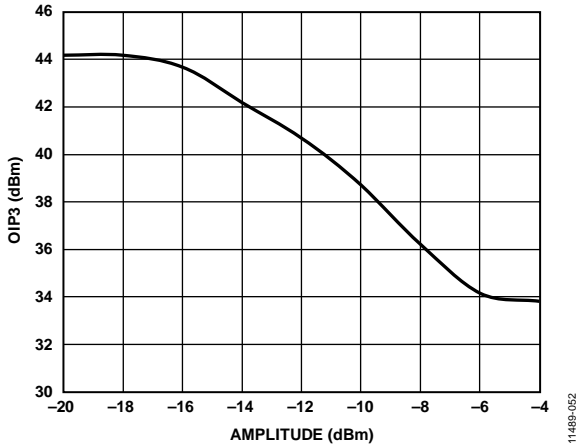


Figure 89. OIP3 vs. ($f_{RF} + f_{LO}$) Amplitude

The ADRF6620 is optimized for use in digital predistortion (DPD) receivers. An example filter design for DPD is shown in Figure 91. Table 17 lists the interstage filter design targets. In most DPD systems for cellular transmission, the pass band is between 50 MHz and 500 MHz. For this reason, the pull-up inductors have a low frequency cutoff of 50 MHz, and the pass-band edge of the interstage low-pass filter is 500 MHz. This results in a band-pass filter profile with a maximally flat pass band from 50 MHz to 500 MHz. The stop-band attenuation at 1400 MHz is 20 dB, which typically provides the necessary attenuation of the mixer sum term with some margin.

Table 17. Example Filter Design

| Parameter | Value |
|-------------------------------|-----------------------|
| R_S | 255 Ω |
| R_L | 150 Ω |
| Pass-Band Edge | 500 MHz |
| Attenuation at Pass-Band Edge | 0.5 dB |
| Stop-Band Edge | 1400 MHz |
| Attenuation at Stop-Band Edge | 20 dB |
| Filter Type | Third-order Chebyshev |

Using filter equations from a textbook or filter design software, a third-order Chebyshev filter can be designed to satisfy all the specifications in Table 17, as shown in Figure 91. The mixer output capacitance of 1.1 pF can be absorbed into the filter, resulting in a reduction in C1 from 2 pF to 0.8 pF. In addition, depending on the PCB board stack-up, C2 can be further reduced, or eliminated, because the capacitance of the PCB board can be used as the third pole of the filter. The components used in the simulation were the Coilcraft 0805CS inductors and Murata GRM15 series capacitors. Figure 90 shows the filter profile that satisfies all the filter specifications in Table 17.

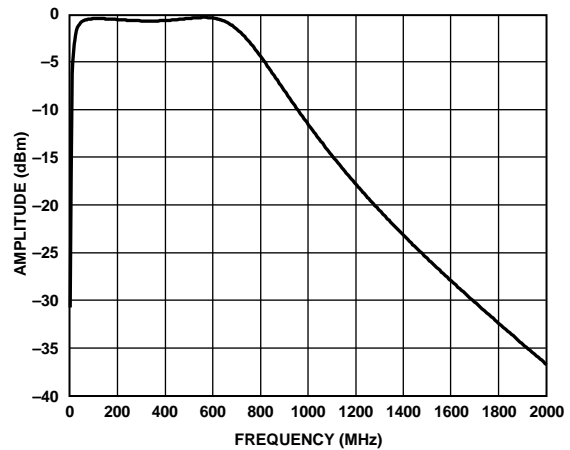


Figure 90. Third-Order Chebyshev Filter Profile

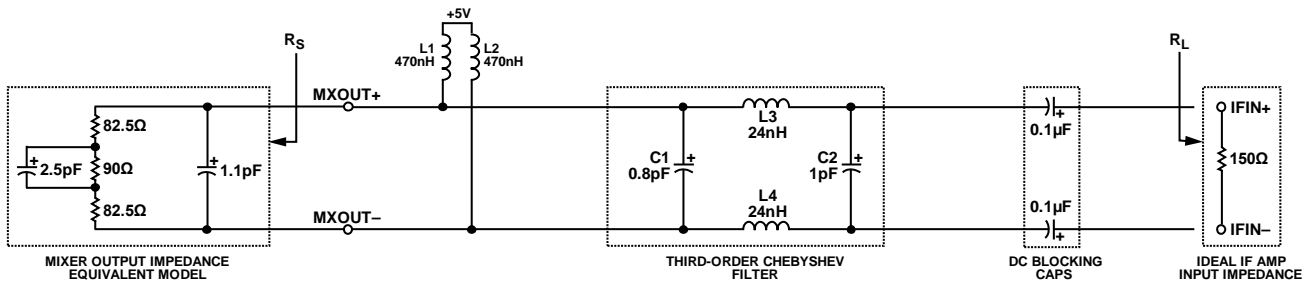


Figure 91. Low-Pass Interstage Filter Design

Maintaining the same third-order Chebyshev filter design shown in Figure 91, the component values can be tuned to optimize performance with some trade-offs. To achieve maximally flat pass-band response, the trade-off is signal bandwidth (see Figure 92). The L3 and L4 inductors are replaced with 47 nH, and the capacitors are not populated. This configuration results in the flattest pass-band ripple; however, the signal bandwidth starts to roll off at 300 MHz. A narrower bandwidth translates to more attenuation of the mixer sum and LO leakage, which is a desirable effect if the wider signal bandwidth is not a requirement. Use the results shown in Figure 92 only as a guide, and design the interstage filter to the specific PCB board conditions. The plots in Figure 92 were measured using the ADRF6620 evaluation board.

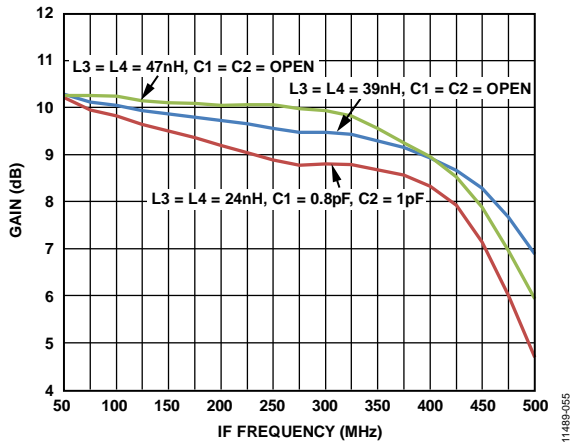


Figure 92. Interstage Filter Design Trade-Offs

Because the capacitance of the ADRF6620 evaluation board closely approximates the C1 and C2 capacitors, they can be removed from the design. However, this may not be the case for every PCB design with different stack-ups.

Figure 93 compares the OIP2 and OIP3 performance of the ADRF6620 with and without filtering at the mixer output.

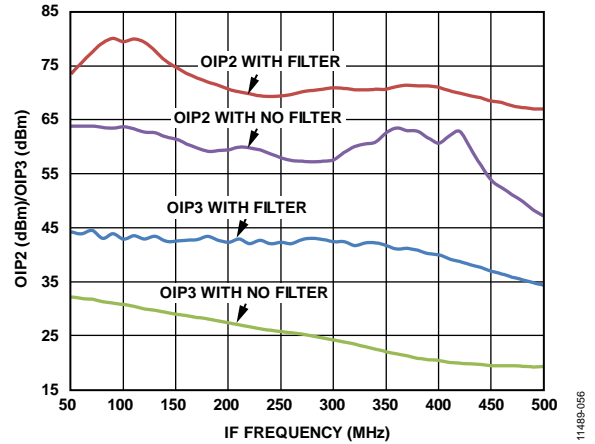


Figure 93. OIP2/OIP3 Performance With and Without Filtering at the DGA Output; RF Frequency = 900 MHz; High-Side LO Injection, LO Sweep

IF DGA VS. LOAD

By design, the IF DGA is optimized for performance in a matched condition where the source and load resistances are both 150 Ω. If the load or the source resistance is not equal to 150 Ω (see the Digitally Programmable Variable Gain Amplifier (DGA) section), use the following equations to determine the resulting gain and input/output resistances:

$$\text{Voltage Gain} = A_V = 0.044 \times (1000 \parallel R_L)$$

$$R_{IN} = (1000 + R_L) / (1 + 0.044 \times R_L)$$

$$S21 (\text{Gain}) = 2 \times R_{IN} / (R_{IN} + R_S) \times A_V$$

$$R_{OUT} = (1000 + R_S) / (1 + 0.044 \times R_S)$$

In a configuration where the mixer outputs of the ADRF6620 are routed to the IF DGA inputs, the matched condition is no longer satisfied because the source impedance, as seen by the IF DGA, is the 255 Ω output impedance of the mixer outputs. As a result, the gain and output resistance of the amplifier vary from the expected 15 dB (see Figure 94).

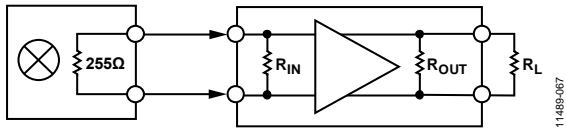


Figure 94. Mixer Loading of the IF DGA

The ideal load is 150 Ω for the matched condition; however, this may not be the most readily available load impedance.

As a result, load vs. performance trade-offs must be considered. In the matched condition, the IF DGA is optimized for linearity; therefore, the third-order intermodulation product degrades with load. Table 18 shows some common output loads, and Figure 95, Figure 96, and Figure 97 show the effects of loading on gain, IMD2, and IMD3.

As the equations in this section indicate, the manner in which the IF DGA is loaded affects the input resistance, R_{IN}, of the amplifier. R_{IN}, in turn, determines the load resistance of the interstage filter between the mixer outputs and the IF DGA inputs. The interstage filter has a source impedance of 255 Ω from the mixer outputs and a load impedance of R_{IN} for the particular R_L load (see Table 18). As a result of the impedance mismatch, the insertion loss of the interstage filter must be included in the level planning calculations.

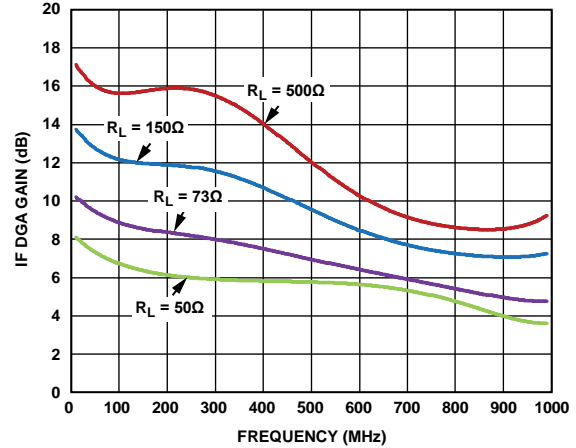


Figure 95. IF DGA Gain vs. Frequency for Different Loads

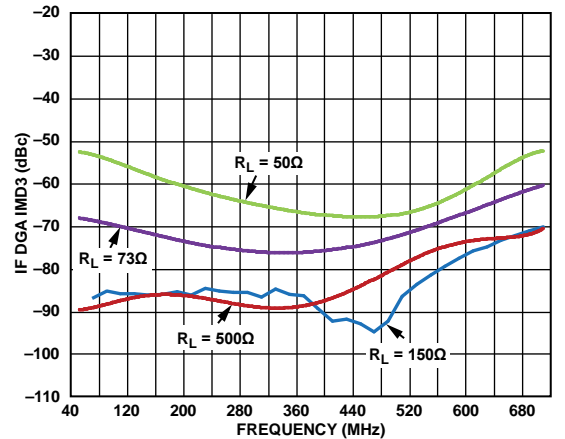


Figure 96. IF DGA IMD3 vs. Frequency for Different Loads

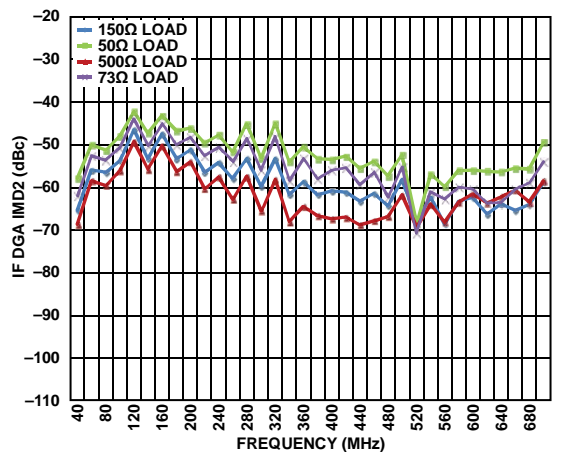


Figure 97. IF DGA IMD2 vs. Frequency for Different Loads

Table 18. Common Output Loads

| R _S (Ω) | R _{IN} (Ω) | A _V (Linear) | A _V (dB) | S21 (Linear) | S21 (dB) | R _{OUT} (Ω) | R _L (Ω) |
|--------------------|---------------------|-------------------------|---------------------|--------------|----------|----------------------|--------------------|
| 255 | 65 | 14.7 | 23.3 | 6 | 15.5 | 102.7 | 500 |
| 255 | 151 | 5.7 | 15.2 | 4.3 | 12.6 | 102.7 | 150 |
| 255 | 255 | 3 | 9.5 | 3 | 9.5 | 102.7 | 73 |
| 255 | 328 | 2.1 | 6.4 | 2.4 | 7.5 | 102.7 | 50 |

ADC INTERFACING

The integrated IF DGA of the [ADRF6620](#) provides variable and sufficient drive capability for both buffered and unbuffered ADCs. It also provides isolation between the sampling edges of the ADC and the mixer core. As result, only an antialiasing filter is required when interfacing with an ADC.

The [ADRF6620](#) is optimized for use in cellular base station digital predistortion (DPD) systems. Predistortion is used to improve the linearity of transmitter power amplifiers (PA). Because the input signal to the DPD path is the known transmitted signal, the hardware specifications are not typically as stringent as the main receive path. The signal-to-noise ratio (SNR) of the ADC is not paramount, due to the autocorrelation with the known transmitted signal. For this reason, lower resolution ADCs are usually adequate, and 11-bit to 14-bit resolution typically suffices. A more critical consideration is the analog bandwidth of the converter. Traditional DPD systems require 3× to 5× the transmit bandwidth. Therefore, for a 100 MHz Tx bandwidth, the DPD bandwidth must be at least 500 MHz for fifth-order correction.

The [AD9434](#) complements the [ADRF6620](#) very well in a DPD design. The [AD9434](#) is a 12-bit, 370 MSPS/500 MSPS buffered ADC. Its full power analog bandwidth is 1 GHz, making it wide enough for fifth-order correction with substantial margin. The sampling rate of the [AD9434](#) is insufficient in satisfying the sampling theorem; however, this may be acceptable in DPD applications where undersampling is often permissible. Because the receive signal in the DPD path is the known transmitted signal, the desired signal and its aliases are clearly distinguished.

The antialiasing filter resides between the [ADRF6620](#) and the [AD9434](#). Because aliasing is common practice in a DPD receive chain, the antialiasing filter requirements can be relaxed. A second-order or third-order filter is sufficient in reducing the high frequency noise from folding back into the band of interest. When designing the antialiasing filter, it is important to consider the output impedance of the IF DGA of the [ADRF6620](#) and the input impedance of the [AD9434](#). The differential resistance of the [AD9434](#) is 1 kΩ, and the parallel capacitance is 1.3 pF. For the matched load condition, where the IF DGA is optimized for gain and linearity, load the IF DGA with 150 Ω. To do this, place a 176 Ω resistor in parallel with the input of the ADC.

The parallel combination of the 176 Ω with the 1 kΩ of the ADC input impedance results in an equivalent 150 Ω differential output load as seen by the IF DGA of the [ADRF6620](#). In addition, the input capacitance of the [AD9434](#) can be used as the fourth pole of the antialiasing filter. The final schematic design is shown in Figure 99. The antialiasing filter is maximally flat, with a pass-band bandwidth of 500 MHz. Table 19 shows the component values for the antialiasing filter design for DPD. Figure 98 shows the simulated antialiasing filter design.

Table 19. Component Values for 500 MHz Antialiasing Filter Design

| Parameter | Value | Type | Manufacturer |
|-----------|--------|--------|--------------|
| L1 = L2 | 470 nH | 0805CS | Coilcraft |
| C1 | DNP | GRM15 | Murata |
| L3 = L4 | 39 nH | 0805CS | Coilcraft |
| C2 | DNP | GRM15 | Murata |
| L5 = L6 | 1 μH | 0805LS | Coilcraft |
| L7 = L8 | 15 nH | 0805CS | Coilcraft |
| C3 | 2.7 pF | GRM15 | Murata |
| L9 = L10 | 27 nH | 0805CS | Coilcraft |

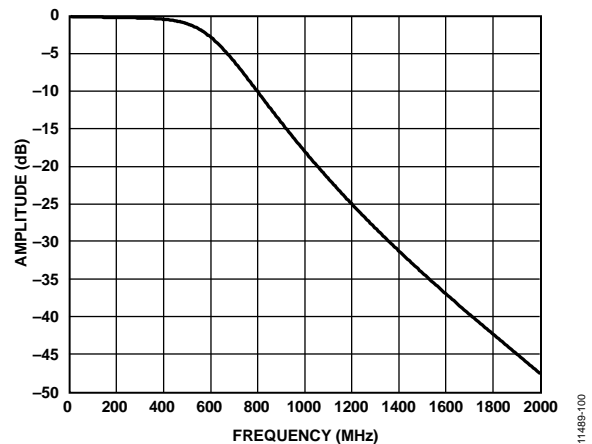


Figure 98. Simulated Antialiasing Filter Design

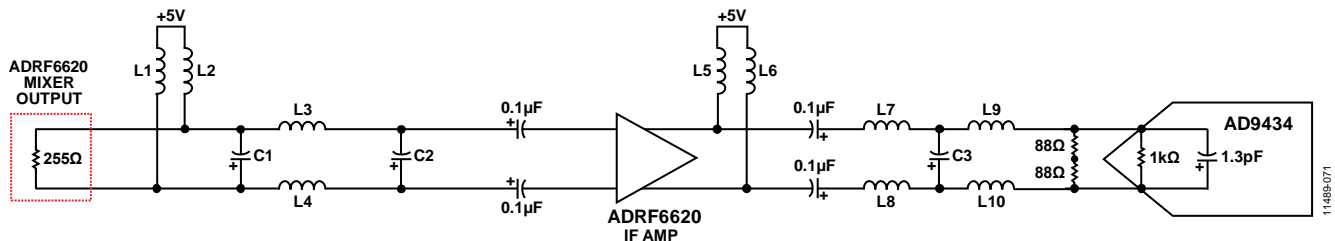


Figure 99. [ADRF6620](#) Interface to the [AD9434](#)

POWER MODES

The ADRF6620 has many building blocks, and these blocks can be independently powered off by writing to Register 0x01 (see Table 23).

External LO Mode

In external LO mode, the internal PLL and VCO are disabled, which reduces the current consumption by approximately 100 mA. Table 20 lists the register settings that are required to configure external LO mode.

Table 20. Serial Port Configuration for External LO Mode

| Bit Name | State | Register |
|------------|-------------|-----------------------|
| LDO_3P3_EN | On | 0x01 = 0x8B53 |
| VCO_LDO_EN | On | 0x01 = 0x8B53 |
| CP_EN | Off | 0x01 = 0x8B53 |
| DIV_EN | Off | 0x01 = 0x8B53 |
| VCO_EN | On | 0x01 = 0x8B53 |
| REF_BUF_EN | Off | 0x01 = 0x8B53 |
| LO_DRV_EN | Off | 0x01 = 0x8B53 |
| LO_PATH_EN | On | 0x01 = 0x8B53 |
| MIX_EN | On | 0x01 = 0x8B53 |
| IF_AMP_EN | On | 0x01 = 0x8B53 |
| LO_LDO_EN | On | 0x01 = 0x8B53 |
| VCO_SEL | External LO | 0x22, Bits[2:0] = 011 |

IF DGA Disable Mode

In applications where the IF DGA is not used, it can be powered down. Power-down is achieved by disabling the IF_AMP_EN bit (Register 0x01, Bit 11 = 0). By disabling the amplifier, the current consumption of the ADRF6620 decreases by approximately 25 mA, along with a 35 mA to 50 mA current savings through each bias inductor at the output of the amplifier. When the IF DGA is disabled, its input and output impedance is high-Z. For this reason, the input and output pins can be left open. If the preference is not to leave the nodes open, the alternative option is to terminate the pins to ground via a 1 kΩ resistor.

LAYOUT

Careful layout of the ADRF6620 is necessary for optimizing performance and minimizing stray parasitics. Because the ADRF6620 supports four RF inputs, the layout of the RF section is critical in achieving isolation between each channel. Figure 100 shows the recommended layout for the RF inputs. Each RF input, RFIN0 to RFIN3, is isolated between ground pins, and the best layout approach is to keep the traces short and direct. To achieve this layout, connect the pins directly to the center ground pad of the exposed pad of the ADRF6620. This approach minimizes the trace inductance and promotes better isolation between the channels. In addition, for improved isolation, do not route the RFIN0 to RFIN3 traces in parallel to each other; instead, spread the traces immediately after each one leaves the pins. Keep the

traces as far away from each other as possible (and at an angle, if possible) to prevent cross coupling.

The input impedance of the RF inputs is 50 Ω, and the traces leading to the pin must also have a 50 Ω characteristic impedance. Terminate unused RF inputs with a dc blocking capacitor to ground.

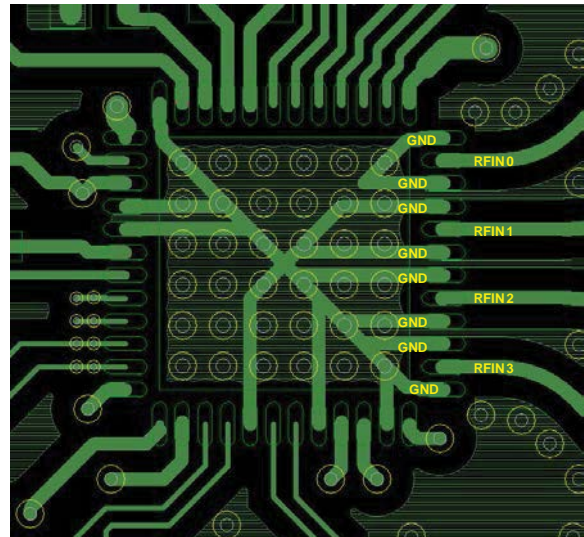


Figure 100. Recommended Layout for the RF Inputs

The IF DGA outputs on the ADRF6620 have two output pins for each polarity, and they are oriented in an alternating fashion, as follows: IFOUT1+ (Pin 8), IFOUT1- (Pin 9), IFOUT2+ (Pin 10), and IFOUT2- (Pin 11). When designing the board, minimize the parasitic capacitance due to the routing that connects the corresponding outputs together. A good practice is to avoid any ground or power plane under this routing region and under the chokes to minimize the parasitic capacitance. Figure 101 shows the recommended layout. The IF DGA output pins with the same polarity are tied together on the bottom of the board with the blue traces and vias.

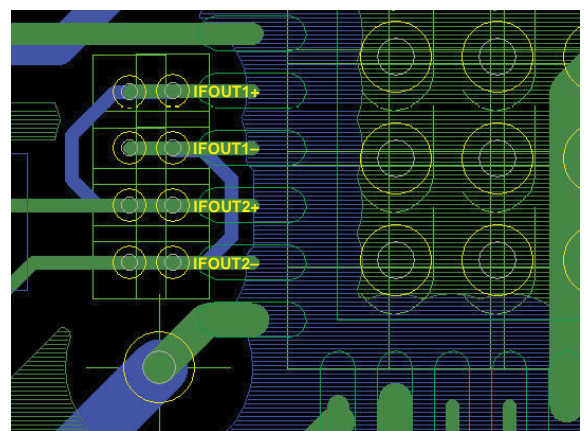


Figure 101. Recommended Layout for the IF DGA Outputs (Green traces are routings on top of the board, and blue traces are routings on the bottom of the board.)

REGISTER MAP

Table 21. Register Map Summary Table

| Reg | Name | Bits | Bit 15 | Bit 14 | Bit 13 | Bit 12 | Bit 11 | Bit 10 | Bit 9 | Bit 8 | Reset | RW | | |
|------|------------|--------|-----------------|-------------|------------|----------|--------------|----------------|------------|---------------|---------------|---------|---------|----|
| | | | Bit 7 | Bit 6 | Bit 5 | Bit 4 | Bit 3 | Bit 2 | Bit 1 | Bit 0 | | | | |
| 0x00 | SOFT_RESET | [15:8] | RESERVED | | | | | | | | | 0x00000 | W | |
| | | [7:0] | RESERVED | | | | | | | | SOFT_RESET | | | |
| 0x01 | Enables | [15:8] | LO_LDO_EN | RESERVED | RESERVED | RESERVED | IF_AMP_EN | RESERVED | MIX_EN | LO_PATH_EN | 0x8B7F | RW | | |
| | | [7:0] | LO_DRV_EN | RESERVED | REF_BUF_EN | VCO_EN | DIV_EN | CP_EN | VCO_LDO_EN | LDO_3P3_EN | | | | |
| 0x02 | INT_DIV | [15:8] | RESERVED | | | | DIV_MODE | INT_DIV[10:8] | | | | 0x0058 | RW | |
| | | [7:0] | INT_DIV[7:0] | | | | | | | | | | | |
| 0x03 | FRAC_DIV | [15:8] | RESERVED | | | | | FRAC_DIV[10:8] | | | | | 0x0250 | RW |
| | | [7:0] | FRAC_DIV[7:0] | | | | | | | | | | | |
| 0x04 | MOD_DIV | [15:8] | RESERVED | | | | | MOD_DIV[10:8] | | | | | 0x0600 | RW |
| | | [7:0] | MOD_DIV[7:0] | | | | | | | | | | | |
| 0x20 | CP_CTL | [15:8] | RESERVED | RESERVED | CSCALE | | | | RESERVED | | | | 0x0C26 | RW |
| | | [7:0] | RESERVED | | BLEED_DIR | BLEED | | | | | | | | |
| 0x21 | PFD_CTL | [15:8] | RESERVED | | | | | | | | | 0x0003 | RW | |
| | | [7:0] | RESERVED | REF_MUX_SEL | | | PFD_POLARITY | REFSEL | | | | | | |
| 0x22 | FLO_CTL | [15:8] | RESERVED | | | | | | | | LO_DRV_LVL[1] | 0x000A | RW | |
| | | [7:0] | LO_DRV_LVL[0] | RESERVED | | | LO_DIV_A | | VCO_SEL | | | | | |
| 0x23 | DGA_CTL | [15:8] | RESERVED | | | | RFSW_MUX | RFSW_SEL | | RFDSA_SEL[3] | 0x0000 | RW | | |
| | | [7:0] | RFDSA_SEL[2:0] | | | IF_ATTEN | | | | | | | | |
| 0x30 | BALUN_CTL | [15:8] | RESERVED | | | | | | | | | | 0x00000 | RW |
| | | [7:0] | BAL_COUT | | | RESERVED | BAL_CIN | | | RESERVED | | | | |
| 0x31 | MIXER_CTL | [15:8] | RESERVED | | | | MIXER_BIAS | | | MIXER_RDAC[3] | | | 0x08EF | RW |
| | | [7:0] | MIXER_RDAC[2:0] | | | RESERVED | MIXER_CDAC | | | | | | | |
| 0x40 | PFD_CTL2 | [15:8] | RESERVED | | | | | | | | | | 0x0010 | RW |
| | | [7:0] | RESERVED | ABLDLY | | CPCTRL | | | CLKEDGE | | | | | |
| 0x42 | DITH_CTL1 | [15:8] | RESERVED | | | | | | | | | | 0x000E | RW |
| | | [7:0] | RESERVED | | | | DITH_EN | DITH_MAG | | DITH_VAL | | | | |
| 0x43 | DITH_CTL2 | [15:8] | DITH_VAL[15:8] | | | | | | | | | | 0x0001 | RW |
| | | [7:0] | DITH_VAL[7:0] | | | | | | | | | | | |

REGISTER ADDRESS DESCRIPTIONS

REGISTER 0x00, RESET: 0x00000, NAME: SOFT_RESET

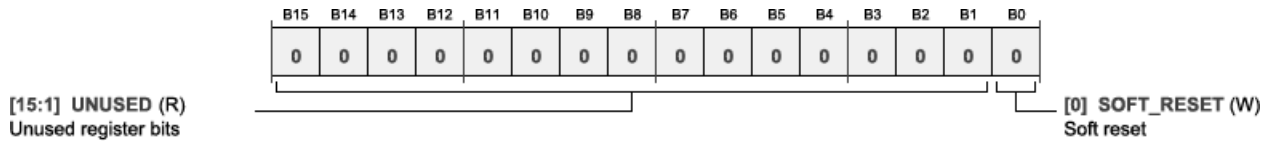


Table 22. Bit Descriptions for SOFT_RESET

| Bit | Bit Name | Settings | Description | Reset | Access |
|-----|------------|----------|-------------|--------|--------|
| 0 | SOFT_RESET | | Soft reset | 0x0000 | W |

REGISTER 0x01, RESET: 0x8B7F, NAME: ENABLES

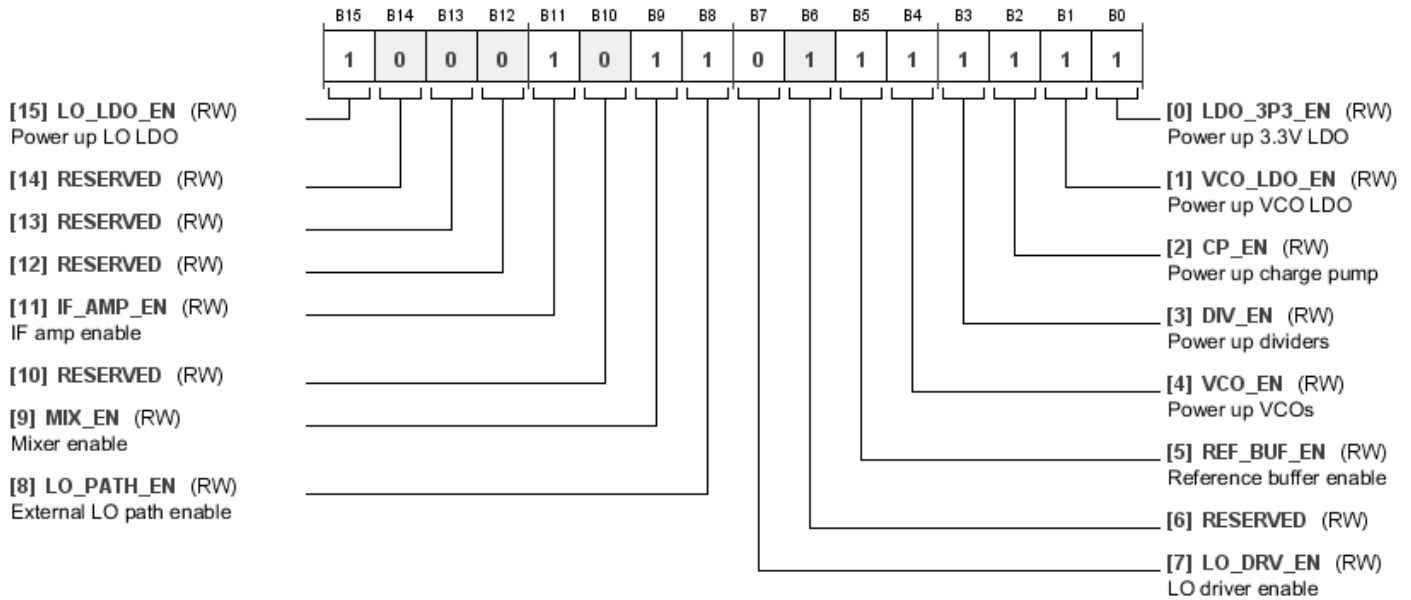


Table 23. Bit Descriptions for Enables

| Bits | Bit Name | Settings | Description | Reset | Access |
|------|------------|----------|-------------------------|-------|--------|
| 15 | LO_LDO_EN | | Power up LO LDO | 0x1 | RW |
| 11 | IF_AMP_EN | | IF DGA enable | 0x1 | RW |
| 9 | MIX_EN | | Mixer enable | 0x1 | RW |
| 8 | LO_PATH_EN | | External LO path enable | 0x1 | RW |
| 7 | LO_DRV_EN | | LO driver enable | 0x0 | RW |
| 5 | REF_BUF_EN | | Reference buffer enable | 0x1 | RW |
| 4 | VCO_EN | | Power up VCOs | 0x1 | RW |
| 3 | DIV_EN | | Power up dividers | 0x1 | RW |
| 2 | CP_EN | | Power up charge pump | 0x1 | RW |
| 1 | VCO_LDO_EN | | Power up VCO LDO | 0x1 | RW |
| 0 | LDO_3P3_EN | | Power up 3.3 V LDO | 0x1 | RW |

REGISTER 0x02, RESET: 0x0058, NAME: INT_DIV

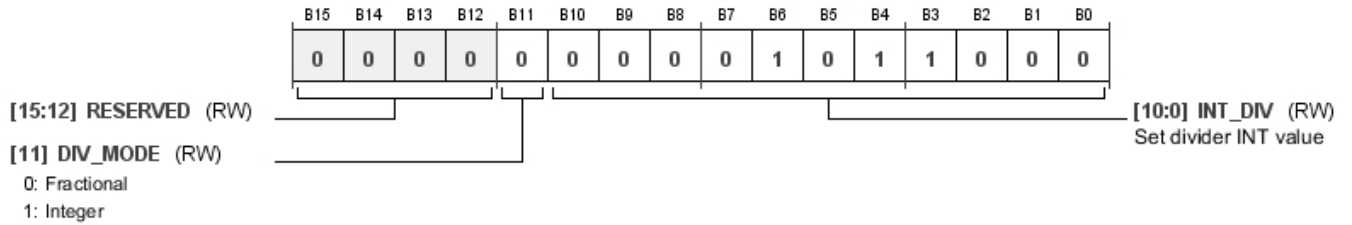


Table 24. Bit Descriptions for INT_DIV

| Bits | Bit Name | Settings | Description | Reset | Access |
|--------|----------|----------|-----------------------|-------|--------|
| 11 | DIV_MODE | 0 1 | Fractional Integer | 0x0 | RW |
| [10:0] | INT_DIV | | Set divider INT value | 0x58 | RW |

REGISTER 0x03, RESET: 0x0250, NAME: FRAC_DIV

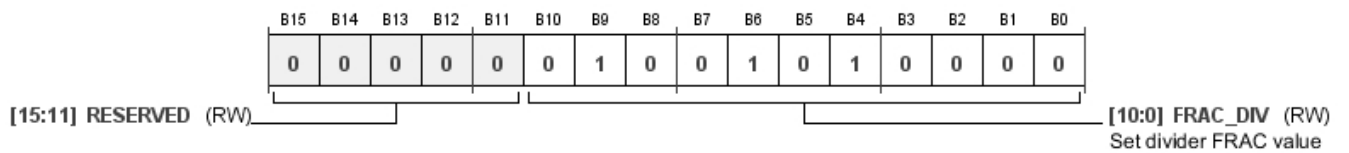


Table 25. Bit Descriptions for FRAC_DIV

| Bits | Bit Name | Settings | Description | Reset | Access |
|--------|----------|----------|------------------------|-------|--------|
| [10:0] | FRAC_DIV | | Set divider FRAC value | 0x250 | RW |

REGISTER 0x04, RESET: 0x0600, NAME: MOD_DIV

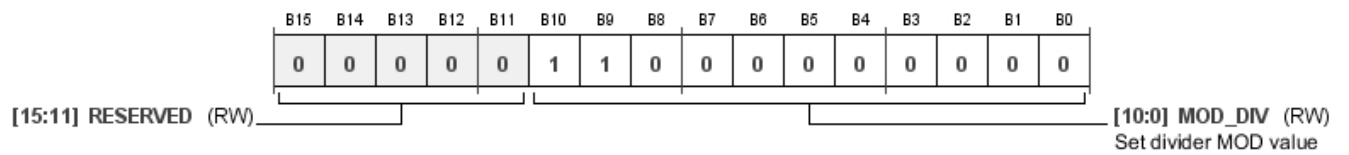


Table 26. Bit Descriptions for MOD_DIV

| Bits | Bit Name | Settings | Description | Reset | Access |
|--------|----------|----------|-----------------------|-------|--------|
| [10:0] | MOD_DIV | | Set divider MOD value | 0x600 | RW |

REGISTER 0x20, RESET: 0x0C26, NAME: CP_CTL

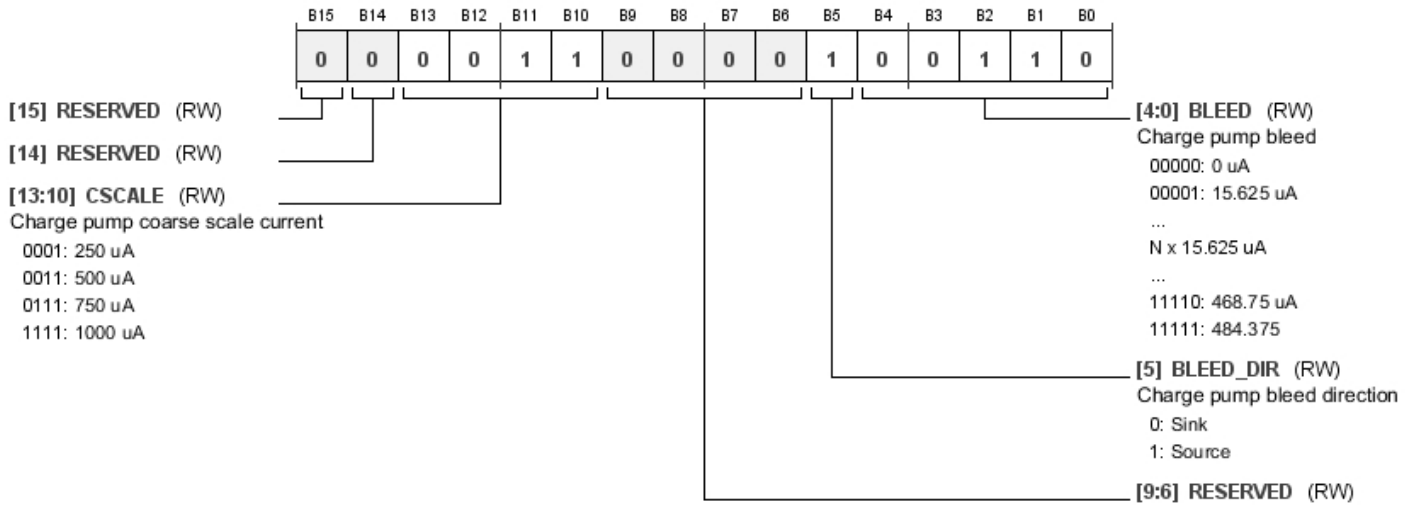


Table 27. Bit Descriptions for CP_CTL

| Bits | Bit Name | Settings | Description | Reset | Access |
|---------|-----------|--|---|-------|--------|
| [13:10] | CSCALE | 0001 0011 0111 1111 | Charge pump current 250 μ A 500 μ A 750 μ A 1000 μ A | 0x3 | RW |
| 5 | BLEED_DIR | 0 1 | Charge pump bleed direction Sink Source | 0x1 | RW |
| [4:0] | BLEED | 00000 00001 11110 11111 | Charge pump bleed 0 μ A 15.625 μ A ... N x 15.625 μ A ... 468.75 μ A 484.375 μ A | 0x06 | RW |

REGISTER 0x21, RESET: 0x0003, NAME: PFD_CTL

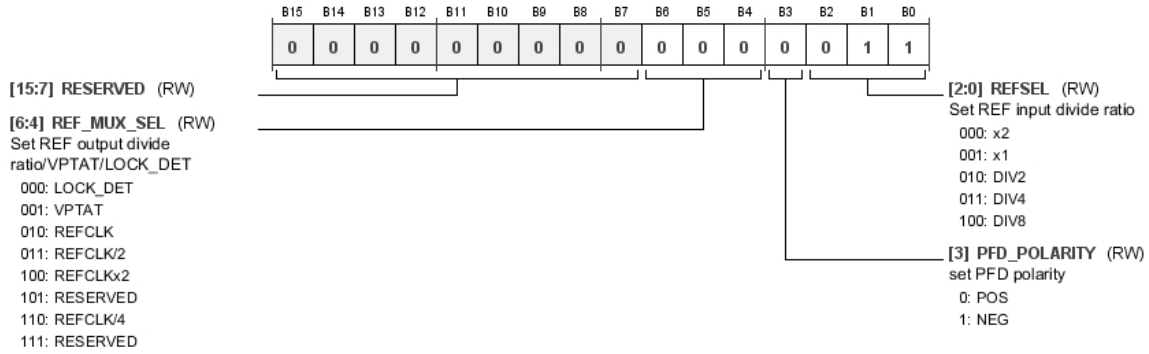


Table 28. Bit Descriptions for PFD_CTL

| Bits | Bit Name | Settings | Description | Reset | Access |
|-------|--------------|--|---|-------|--------|
| [6:4] | REF_MUX_SEL | 000 001 010 011 100 101 110 111 | Set REF output divide ratio/VPTAT/LOCK_DET LOCK_DET VPTAT REFCLK REFCLK/2 REFCLK × 2 RESERVED REFCLK/4 RESERVED | 0x0 | RW |
| 3 | PFD_POLARITY | 0 1 | Set PFD polarity Positive K _v VCO Negative K _v VCO | 0x0 | RW |
| [2:0] | REFSEL | 000 001 010 011 100 | Set REF input divide ratio ×2 ×1 DIV2 DIV4 DIV8 | 0x3 | RW |

REGISTER 0x22, RESET: 0x000A, NAME: FLO_CTL

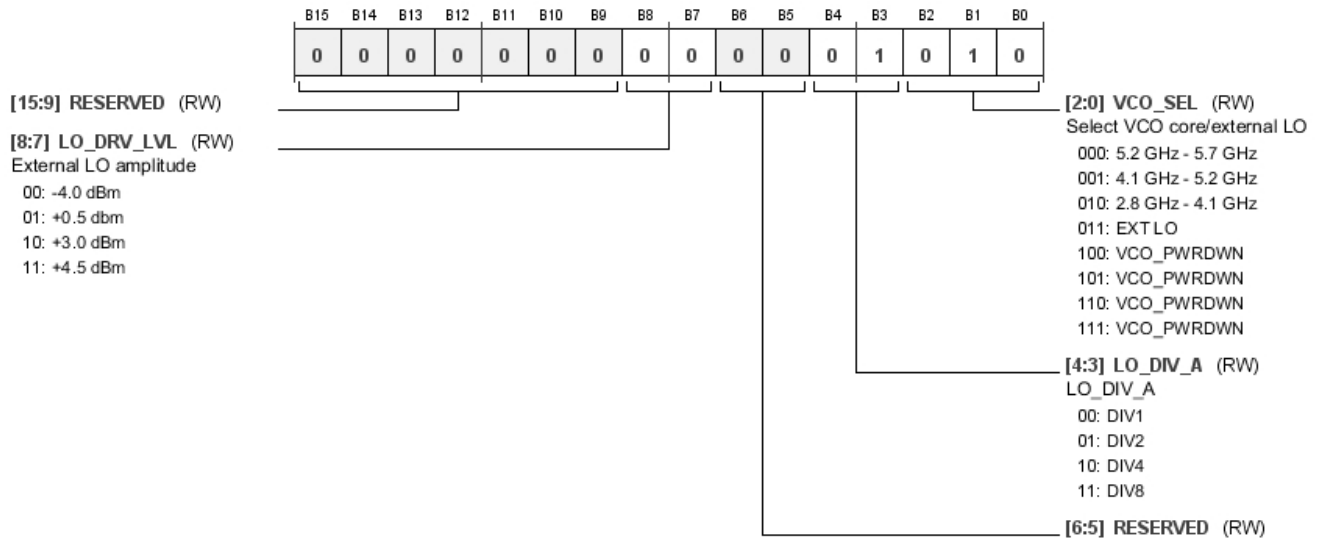


Table 29. Bit Descriptions for FLO_CTL

| Bits | Bit Name | Settings | Description | Reset | Access |
|-------|------------|--|---|-------|--------|
| [8:7] | LO_DRV_LVL | 00 01 10 11 | LO amplitude -4 dBm 0.5 dBm +3 dBm +4.5 dBm | 0x0 | RW |
| [4:3] | LO_DIV_A | 00 01 10 11 | LO_DIV_A DIV1 DIV2 DIV4 DIV8 | 0x1 | RW |
| [2:0] | VCO_SEL | 000 001 010 011 100 101 110 111 | Select VCO core/external LO 5.2 GHz to 5.7 GHz 4.1 GHz to 5.2 GHz 2.8 GHz to 4.1 GHz EXT LO VCO_PWRDWN VCO_PWRDWN VCO_PWRDWN VCO_PWRDWN | 0x2 | RW |

REGISTER 0x23, RESET: 0x0000, NAME: DGA_CTL

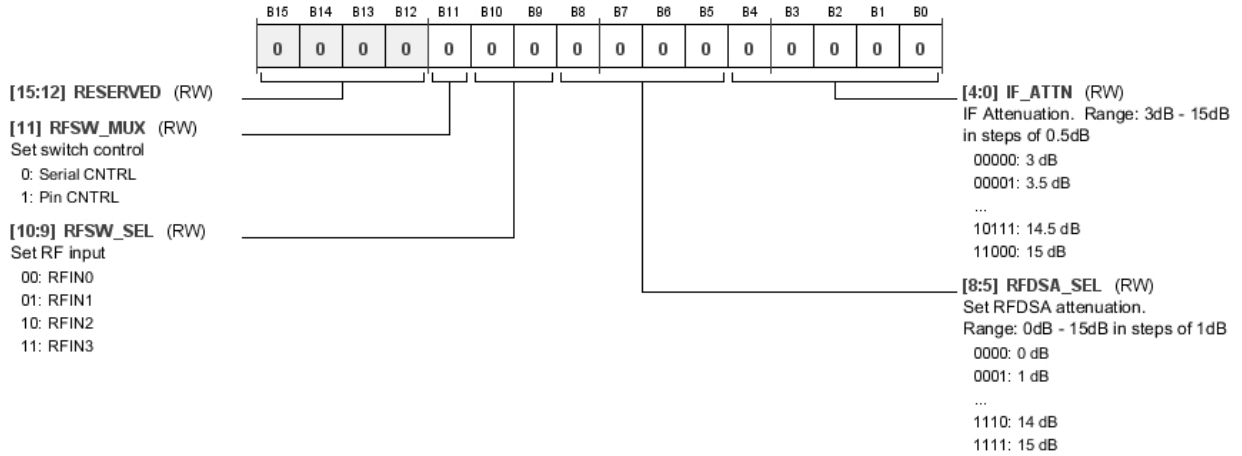


Table 30. Bit Descriptions for DGA_CTL

| Bits | Bit Name | Settings | Description | Reset | Access |
|--------|-----------|---|--|-------|--------|
| 11 | RFSW_MUX | 0 1 | Set switch control. Serial CNTRL Pin CNTRL | 0x0 | RW |
| [10:9] | RFSW_SEL | 00 01 10 11 | Set RF input. RFIN0 RFIN1 RFIN2 RFIN3 | 0x0 | RW |
| [8:5] | RFDSA_SEL | 0000 0001 ... 1110 1111 | Set RFDSA attenuation. Range: 0 dB to 15 dB in steps of 1 dB. 0 dB 1 dB ... 14 dB 15 dB | 0x0 | RW |
| [4:0] | IF_ATTN | 00000 00001 ... 10111 11000 | IF Attenuation. Range: 3 dB to 15 dB in steps of 0.5 dB. 3 dB 3.5 dB ... 14.5 dB 15 dB | 0x0 | RW |

REGISTER 0x30, RESET: 0x00000, NAME: BALUN_CTL

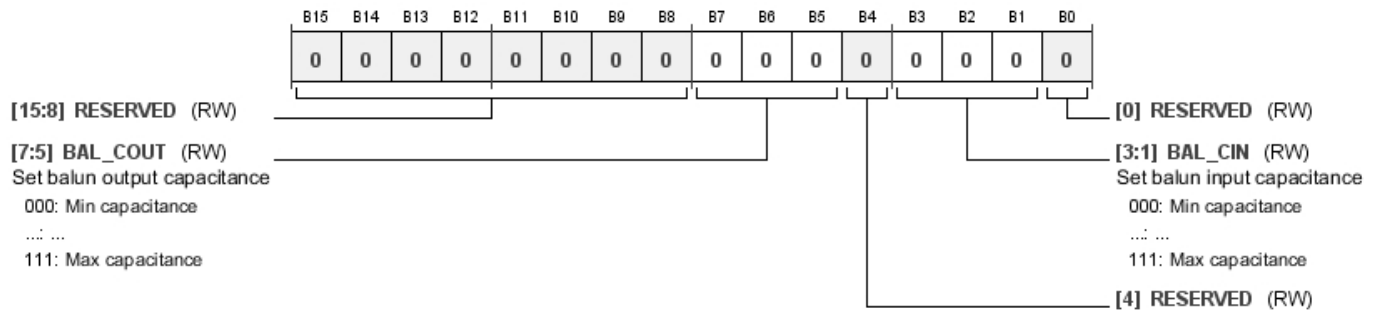


Table 31. Bit Descriptions for BALUN_CTL

| Bits | Bit Name | Settings | Description | Reset | Access |
|-------|----------|-------------------|---|-------|--------|
| [7:5] | BAL_COUT | 000 ... 111 | Set balun output capacitance Minimum capacitance ... Maximum capacitance | 0x0 | RW |
| [3:1] | BAL_CIN | 000 ... 111 | Set balun input capacitance Minimum capacitance ... Maximum capacitance | 0x0 | RW |

REGISTER 0x31, RESET: 0x08EF, NAME: MIXER_CTL

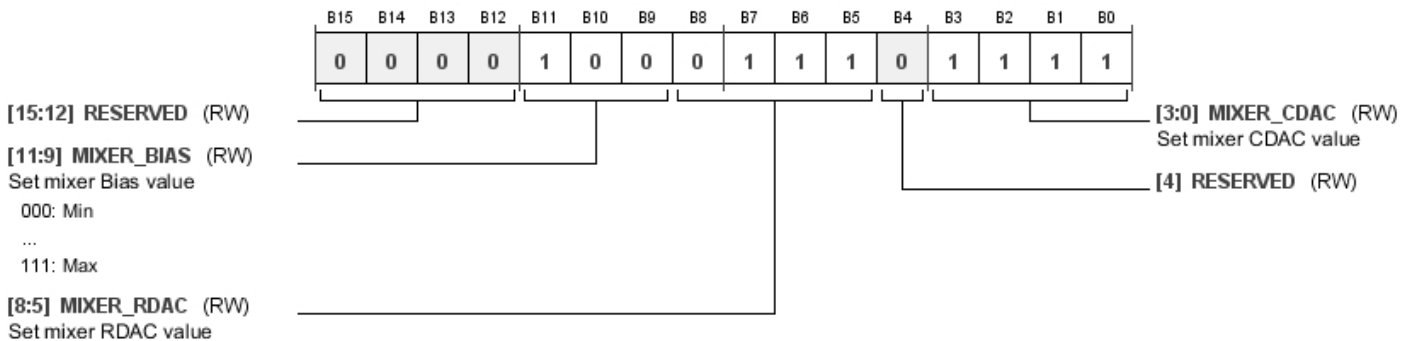


Table 32. Bit Descriptions for MIXER_CTL

| Bits | Bit Name | Settings | Description | Reset | Access |
|--------|------------|-------------------|---|-------|--------|
| [11:9] | MIXER_BIAS | 000 ... 111 | Set mixer bias value Minimum ... Maximum | 0x4 | RW |
| [8:5] | MIXER_RDAC | | Set mixer RDAC value | 0x7 | RW |
| [3:0] | MIXER_CDAC | | Set mixer CDAC value | 0xF | RW |

REGISTER 0x40, RESET: 0x0010, NAME: PFD_CTL2

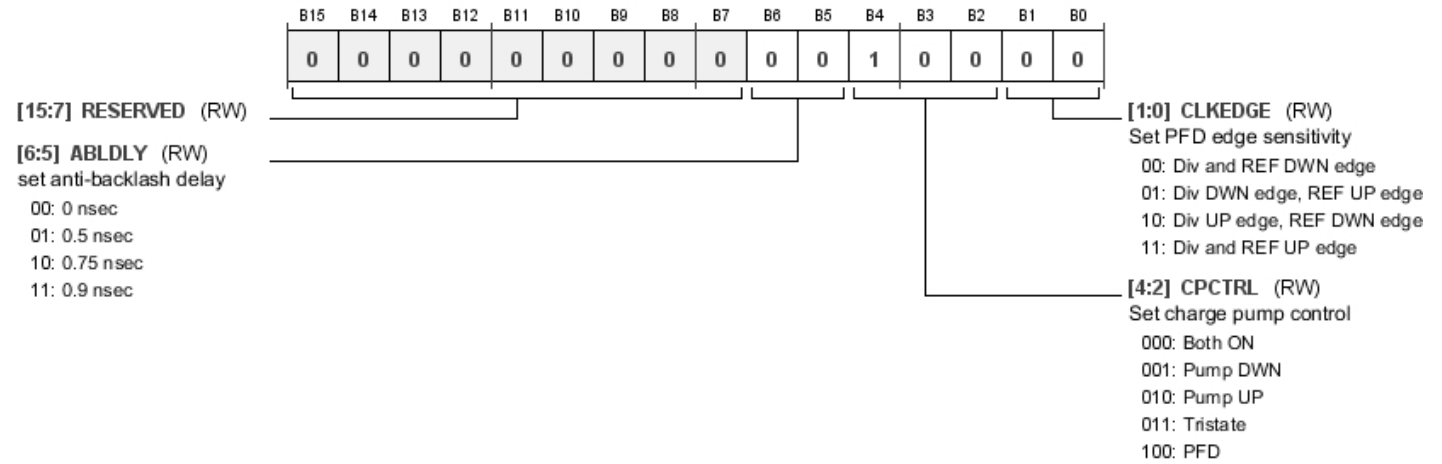


Table 33. Bit Descriptions for PFD_CTL2

| Bits | Bit Name | Settings | Description | Reset | Access |
|-------|----------|---------------------------------|--|-------|--------|
| [6:5] | ABLDLY | 00 01 10 11 | Set antibacklash delay 0 ns 0.5 ns 0.75 ns 0.9 ns | 0x0 | RW |
| [4:2] | CPCTRL | 000 001 010 011 100 | Set charge pump control. Both on Pump down Pump up Tristate PFD | 0x4 | RW |
| [1:0] | CLKEDGE | 00 01 10 11 | Set PFD edge sensitivity Div and REF down edge Div down edge, REF up edge Div up edge, REF down edge Div and REF up edge | 0x0 | RW |

REGISTER 0x42, RESET: 0x000E, NAME: DITH_CTL1

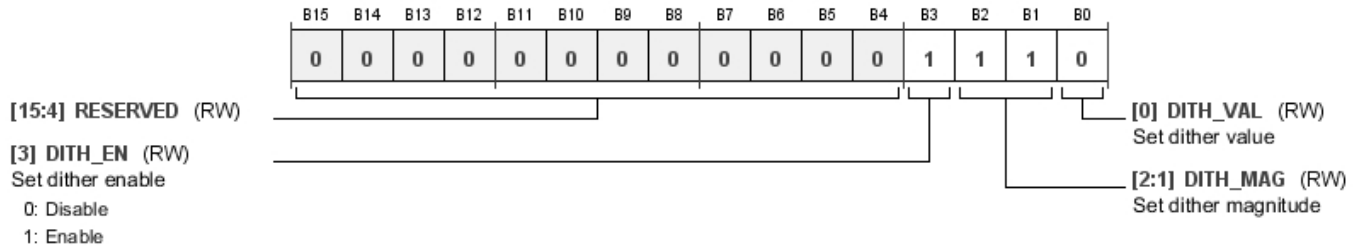


Table 34. Bit Descriptions for DITH_CTL1

| Bits | Bit Name | Settings | Description | Reset | Access |
|-------|----------|----------|--|-------|--------|
| 3 | DITH_EN | 0 1 | Set dither enable Disable Enable | 0x1 | RW |
| [2:1] | DITH_MAG | | Set dither magnitude | 0x3 | RW |
| 0 | DITH_VAL | | Set dither value | 0x0 | RW |

REGISTER 0x43, RESET: 0x0001, NAME: DITH_CTL2

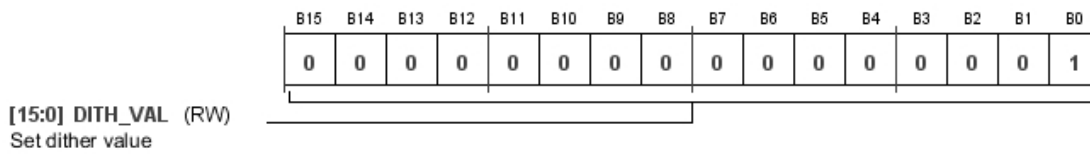
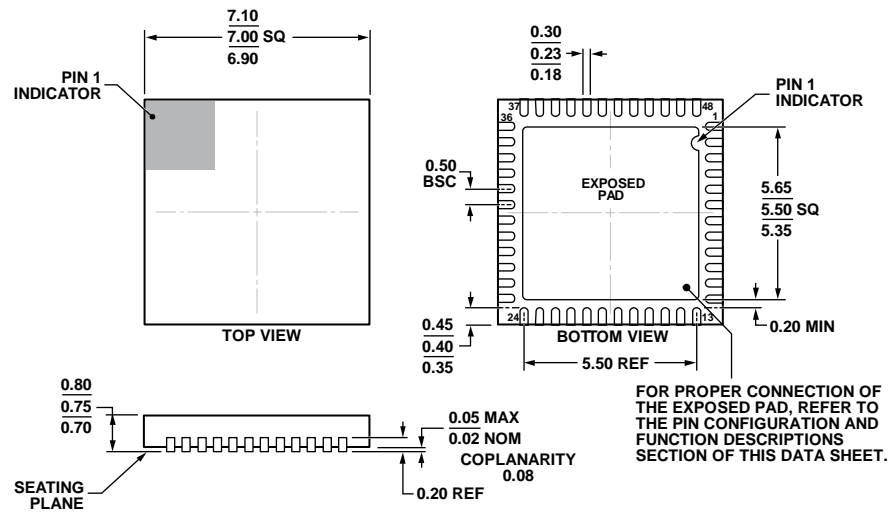


Table 35. Bit Descriptions for DITH_CTL2

| Bits | Bit Name | Settings | Description | Reset | Access |
|--------|----------|----------|------------------|-------|--------|
| [15:0] | DITH_VAL | | Set dither value | 0x1 | RW |

OUTLINE DIMENSIONS



06-06-2012-B

COMPLIANT TO JEDEC STANDARDS MO-220-WKKD.

Figure 102. 48-Lead Lead Frame Chip Scale Package [LFCSP_WQ]
 7 mm × 7 mm Body, Very Very Thin Quad
 (CP-48-9)
 Dimensions shown in millimeters

ORDERING GUIDE

| Model ¹ | Temperature Range | Package Description | Package Option |
|--------------------|-------------------|--|----------------|
| ADRF6620ACPZ-R7 | -40°C to +85°C | 48-Lead Lead Frame Chip Scale Package [LFCSP_WQ] | CP-48-9 |
| ADRF6620-EVALZ | | Evaluation Board | |

¹ Z = RoHS Compliant Part.

NOTES

Mouser Electronics

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